Overview

HP Z6 G4 Workstation



Front view

- 1. Integrated Front Handle
- 2. Front I/O module options
 - Premium (optional, shown here): power button,
 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C™
 (Left-most Type A port has charging capability),
 Headset/Mic, Media Card Reader (optional).
 - Standard: power button, 4 USB 3.1 G1 Type-A (left-most Type A port has charging capability), Headset/Mic, Media Card Reader (optional).
- 3. 2 x 5.25" external bays
- 4. 1 Slim ODD bay

Overview

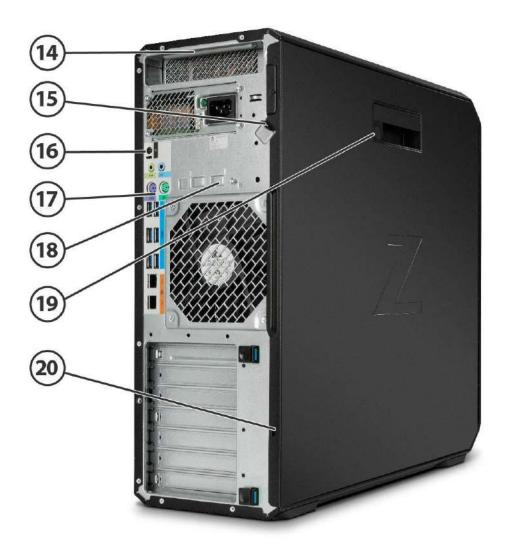


Internal view

- 5. Power supply: 1000W 90% efficient with 2 graphics power adapters
- 6. 6 DIMM slots: DDR4-2666 Registered RAM
- 7. Intel® Xeon® processor Scalable family
- 8. 2nd CPU & memory riser connector: adds 2nd CPU socket and (6) DIMM slots
- 9. PCIe slots: 2 PCIe G3 x16, 3 PCIe G3 x4, 1 PCIe G3 x8

- 10. 6 x 6Gb/s SATA ports
- 11. 2 PCle G3 x4 M.2 for SSDs
- 12. 2 x 2.5"/3.5" internal drive bays
- 13. 2 x 5.25" external drive bays

Overview



- 14. Rear handle
- 15. Padlock loop
- 16. Rear power button
- 17. Rear I/O (top to bottom): audio in/out, keyboard/mouse PS/2, 6 USB 3.1 G1 Type-A, 2 x 1GbE LAN ports

Rear view

- 18. HP Dual Port 10GBase-T NIC module slot (optional)
- 19. Side panel barrel keylock (optional)
- 20. Kensington lock slot

Overview

Overview

Form Factor Operating Systems

Tower

Preinstalled:

- Windows 11 Pro for Workstations²
- Windows 10 Pro for Workstations^{1,2}
- Ubuntu 20.04 LTS³
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1 year support; no preinstalled OS)

Supported:

- Red Hat Enterprise Linux Workstation 6, 7, 84
- SUSE Linux Enterprise Desktop 12, 15⁴
- Ubuntu 16.04, 18.04, 20.04 LTS³

²Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for updates.

⁴**Notes**: For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: In accordance with Microsoft's support policy, HP does not support the Windows® 7 operating system on products configured with Intel® 7th Generation and forward processors.

Available Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Intel® Turbo Boost Technology¹	Supports Intel® DCPMM Technology ²	TDP (W)			
Intel® Xeon® W Processors											
Intel® Xeon® W-3265 processor	24	2.7 GHz	33	2933	Yes	4.4, 4.6	NO	205			
Intel® Xeon® W-3245 processor	16	3.2 GHz	22	2933	YES	4.4, 4.6	NO	205			
Intel® Xeon® W-3225 processor	8	3.7 GHz	16.5	2666	YES	4.3, 4.4	NO	160			
Intel® Xeon® W-3223 processor	8	3.5 GHz	16.5	2666	YES	4, 4.2	NO	160			
Intel® Xeon® Scalable Processors											
Intel® Xeon® Gold 6258R processor	28	2.7 GHz	38.50	2933	YES	4.0, 3.4	YES	205			



¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

Overview

Intel® Xeon® Gold 6248R processor	24	3.0 GHz	35.75	2933	YES	4.0, 3.9	YES	205
Intel® Xeon® Gold 6246R processor	16	3.4 GHz	35.75	2933	YES	4.1, 4.0	YES	205
Intel® Xeon® Gold 6244 processor	8	3.6 GHz	24.75	2933	YES	4.3, 4.4	YES	150
Intel® Xeon® Gold 6242R processor	20	3.1 GHz	35.75	2933	YES	4.1, 3.8	YES	205
Intel® Xeon® Gold 6242 processor	16	2.6 GHz	22	2933	YES	3.5, 3.9	YES	150
Intel® Xeon® Gold 6240 processor	18	2.6 GHz	24.75	2933	YES	3.3, 3.9	YES	150
Intel® Xeon® Gold 6234 processor	8	3.3 GHz	24.75	2933	YES	4.0, 4.0	YES	130
Intel® Xeon® Gold 6230R processor	26	2.1 GHz	35.75	2933	YES	4.0, 3.0	YES	150
Intel® Xeon® Gold 6226R processor	16	2.9 GHz	22	2933	YES	3.9, 3.6	YES	150
Intel® Xeon® Gold 6226 processor	12	2.7 GHz	19.25	2933	YES	3.5, 3.7	YES	125
Intel® Xeon® Gold 6136 processor	12	3.0 GHz	24.75	2666	YES	3.6, 3.7	NO	150
Intel® Xeon® Gold 6128 processor	6	3.4 GHz	19.25	2666	YES	3.7, 3.7	NO	115
Intel® Xeon® Gold 5222 processor	4	3.8 GHz	16.5	2933	YES	3.9, 3.9	YES	105
Intel® Xeon® Gold 5220R processor	24	2.2 GHz	35.75	2666	YES	4.0, 2.9	YES	150
Intel® Xeon® Gold 5218R processor	20	2.1GHz	27.5	2666	YES	4.0, 2.9	YES	125
Intel® Xeon® Gold 5218 processor	16	2.3 GHz	22	2666	YES	2.8, 3.9	YES	125
Intel® Xeon® Gold 5118 processor	12	2.3 GHz	16.50	2400	YES	2.7, 3.2	NO	105
Intel® Xeon® Silver 4216 processor	16	2.1 GHz	22	2400	YES	2.7, 3.2	NO	100
Intel® Xeon® Silver 4215R processor	8	3.2 GHz	11	2400	YES	4.0, 3.6	YES	130
Intel® Xeon® Silver 4214R processor	12	2.4 GHz	16.5	2400	YES	3.0, 3.5	NO	100
Intel® Xeon® Silver 4214 processor	12	2.2 GHz	16.5	2400	YES	2.7, 3.2	NO	85
Intel® Xeon® Silver 4210R processor	10	2.4 GHz	13.75	2400	YES	2.9, 3.2	NO	100
Intel® Xeon® Silver 4210 processor	10	2.2 GHz	13.75	2400	YES	2.7, 3.2	NO	85
Intel® Xeon® Silver 4208 processor	8	2.1 GHz	11	2400	YES	2.5, 3.2	NO	85
Intel® Xeon® Silver 4114 processor	10	2.2 GHz	13.75	2400	YES	2.5, 3.0	NO	85
Intel® Xeon® Silver 4108 processor	8	1.8 GHz	11.00	2400	YES	2.1, 3.0	NO	85
Intel® Xeon® Bronze 3206R processor	8	1.9 GHz	11.00	2133	YES	N/A	NO	85
Intel® Xeon® Bronze 3204 processor	6	1.9 GHz	8.25	2133	YES	N/A	NO	85



Overview

All Z6G4 Intel® Xeon® CPUs Feature Intel® vPro™ Technology.
¹ The specifications shown in this column represent the following: (all core maximum turbo frequency, one core maximum turbo frequency). Processors that do not have turbo functionality are denoted as N/A.
² Intel® Data Center Persistent Memory Modules availability will be announced at a future date.

Available Processors

Disclaimers

When ordering two processors, the second processor must be the same as the first. Intel processor numbers are not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families.

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Color Black

Convertibility

No

Expansion Slots (see more details)

Slot 0:

system board section for Mechanical-only, for use with devices that require only rear bulkhead mounting or when 2nd CPU riser is installed

Slot 1:

PCI Express Gen3 x4 - CPU with open-ended connector*

Slot 2:

PCI Express Gen3 x16 - CPU

PCI Express Gen3 x4 - PCH with open-ended connector*

Slot 4:

PCI Express Gen3 x8 - CPU with open-ended connector (slot converts to x4 electrical when SSD is installed in 2nd M.2 slot)*

Slot 5:

PCI Express Gen3 x16 - CPU

Slot 6:

PCI Express Gen3 x4 - PCH with open-ended connector*

M.2 Slot 1:

M.2 PCle Gen 3 x4 - CPU up to 80mm storage devices

M.2 Slot 2:

M.2 PCle Gen 3 x4 - CPU up to 80mm storage devices

* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.



Overview

Expansion Bays (see storage section for mor

2 internal 3.5" bays (with acoustic dampening rail assemblies pre-installed)

storage section for more 2 external 5.25" bays

details)

3rd and 4th 3.5" HDD each occupy one external bay

3rd and 4th 2.5" HDD/SSD occupy a single external bay within a 2:1 carrier)

1 dedicated 9.5mm slim optical disk drive bay

Front I/O

Base: Power button, 1 Headset audio port, 4 USB 3.1 G1 Type A (1 charging)

 Premium (optional): Power button, 1 Headset audio port, 2 USB 3.1 G2 Type C[™], 2 USB 3.1 G1 Type A (1 charging)

Optional: SD reader

Internal I/O

1 USB 3.1 G1 (aka USB 3.0) single-port header, 1 USB 2.0 single-port header and 1 USB 2.0 dual-port

header

Rear I/O

6 USB 3.1 G1 (aka USB 3.0) Type A ports, 2 1Gbe LAN ports (1x supporting Intel® AMT), Audio: 1 Line out, 1 Line in (Line in can be retasked as microphone), 1 PS/2 mouse port, 1 PS/2 keyboard port, 1

Rear power button

Optional: 1 serial port (cable up to rear bulkhead)

Interfaces Supported

SD card reader (optional)

6-channel SATA interface (6 @ 6.0 Gb/s)

6 channels are eSATA configurable for use with eSATA CTO/AMO Kit (No hot plug / hot swap

supported)

USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)

On-board RAID Support

SATA RAID 0 Striped Array SATA RAID 1 Mirrored Array SATA RAID 5 Striped/Parity SATA RAID 10 Striped/Mirrored

Chassis Dimensions (H x H: 17.5" (445mm)

WxD)

W: 6.65" (169mm) D: 18.3" (465mm)

Packaged Dimensions

H: 24" (610mm) W: 12.3" (313mm) D: 23.3" (593mm)

Palletization Profile

6 units x 3 layers = 18 units per pallet 1200x1000x1836mm (pallet included)

Rack Dimensions 4U

Weight

Exact weights depend upon configuration (System weight only).

Minimum: 13.1 kg (29 lbs.) Standard: 13.6 kg (30.1 lbs.) Maximum: 23.9 kg (52.7 lbs.)

Temperature

Operating: 5° to 35°C (40° to 95°F)

Non-operating: -40° to 60°C (-40° to 140°F)

NOTE: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1°C (1.8°F)

per 305 m (1,000 feet) elevation increase

Humidity

Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb



Overview

Maximum Altitude (non- Operating: 3,048m (10,000ft) pressurized)

Non-operating: 9,144m (30,000ft)

NOTE: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1° C (1.8° F)

per 305 m (1,000 feet) elevation increase

Power Supply 1000 watts wide-ranging, active Power Factor Correction, 90% Efficient, with 2X 6-pin graphics power

cables (graphics power cables are 6/8-pin convertible)

The Z6 G4 1000W power supply efficiency report can be found at this link:

https://plugloadsolutions.com/psu_reports/HP_D15-1K0P1A_1000W_ECOS%204838_Report.pdf

NOTE: All power cords supplied by HP for Desktop Workstations are between 1.83m and 2.5m

(dependent on country localization and platform).

Workstation ISV Certifications

See the latest list of certifications at

http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html



Supported Components

Processors

	Factory Configured	Option Kit	Option Kit Part Number ¹	Support Notes
Intel® Xeon® W-3200 Series CPU				
Intel® Xeon® W-3265 2.7 2933 24C processor	Υ	N		
Intel® Xeon® W-3245 3.2 2933 16C processor	Υ	N		
Intel® Xeon® W-3225 3.7 2666 8C processor	Υ	N		
Intel® Xeon® W-3223 3.5 2666 8C processor	Υ	N		
Intel® Xeon® Scalable CPU				
Intel® Xeon® Gold 6258R processor	Υ	N		
Intel® Xeon® Gold 6248R processor	Υ	N		
Intel® Xeon® Gold 6246R processor	Υ	N		
Intel® Xeon® Gold 6244 processor	Υ	Υ	5YT05AA	1
Intel® Xeon® Gold 6242R processor	Υ	N		
Intel® Xeon® Gold 6242 processor	Υ	Υ	5YT04AA	1
Intel® Xeon® Gold 6240 processor	Υ	Υ	5YT02AA	1
Intel® Xeon® Gold 6234 processor	Υ	Υ	5YT00AA	1
Intel® Xeon® Gold 6230R processor	Υ	Υ	9VA87AA	1
Intel® Xeon® Gold 6226R processor	Υ	Υ	9VA85AA	1
Intel® Xeon® Gold 6226 processor	Υ	Υ	5YS98AA	1
Intel® Xeon® Gold 6136 processor	Υ	Υ	1XM39AA	1
Intel® Xeon® Gold 6128 processor	Υ	Υ	1XM44AA	1
Intel® Xeon® Gold 5222 processor	Υ	Υ	5YS97AA	1
Intel® Xeon® Gold 5220R processor	Υ	Υ	8BC99AA/AT	1
Intel® Xeon® Gold 5218R processor	Υ	Υ	9VA83AA	1
Intel® Xeon® Gold 5218 processor	Υ	Υ	5YS95AA	1
Intel® Xeon® Gold 5118 processor	Υ	Υ	1XM45AA	1
Intel® Xeon® Silver 4216 processor	Υ	Υ	5YS93AA	1
Intel® Xeon® Silver 4215R processor	Υ	Υ	9VA81AA	1
Intel® Xeon® Silver 4214R processor	Υ	Υ	8BC96AA/AT	1
Intel® Xeon® Silver 4214 processor	Υ	Υ	5YS91AA	1
Intel® Xeon® Silver 4210R processor	Υ	Υ	8BC95AA	1
Intel® Xeon® Silver 4210 processor	Υ	Υ	5YS90AA	1
Intel® Xeon® Silver 4208 processor	Υ	Υ	5YS89AA	1
Intel® Xeon® Silver 4114 processor	Υ	Υ	1XM49AA	1
Intel® Xeon® Silver 4108 processor	Υ	Υ	1XM51AA	1
Intel® Xeon® Bronze 3206R processor	Υ	Υ	8BC93AA	1
Intel® Xeon® Bronze 3204 processor	Υ	Υ	5YS88AA	1

¹ Options kits available for second processor upgrade.

Disclaimers: When ordering two processors, the second processor must be the same as the first. Intel processor numbers are not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families.

Note 1: Intel® DCPMM® (Data Center Persistent Memory) Supported.



Supported Components

Monitors / Displays		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z Display Z22n G2		Υ	1JS05AA	
	HP Z Display Z23n G2		Υ	1JS06AA	
	HP Z Display Z24i G2		Υ	1JS08AA	
	HP Z Display Z24n G2		Υ	1JS09AA	
	HP Z Display Z24nf G2		Υ	1JS07AA	
	HP Z Display Z27n G2		Υ	1JS10AA	
	HP Z Display Z27s (4K display)		Υ	J3G07AA	
	Supported by all operating systems available from HP Screen size measured diagonally				

Storage / Hard Drives

SAS Hard Drives	SAS Hard Drives for HP Workstations	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	
	HP 300GB 15k SAS SFF	Υ	Υ	L5B74AA		
	NOTE: SAS controller add-in card required					

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	500GB SATA 7200RPM 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA	
	500GB SATA 7200RPM 6Gb/s OPAL2 SFF 3.5" HDD	Υ	Υ	D8N29AA	
	1TB SATA 7200RPM 3.5" HDD	Υ	Υ	LQ037AA	
	1TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM HDD	Υ	Υ	QB576AA	
	2TB 7200RPM SATA 3.5in Enterprise	Υ	Υ	2Z274AA	
	4TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	K4T76AA	
	6TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	3DH90AA	
	8TB 7200RPM SATA 3.5in Enterprise	Υ	Υ	2Z273AA	
	NOTES:				

Up to (4) 3.5-inch 7200 rpm SATA drives: 500 GB, 1.0, 2.0, 4.0 TB; maximum system HDD storage: 16.0TB

Supported Components

SATA Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Solid State Drives (SSDs) for Workstations				
	HP 256GB SATA SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	Υ	Υ	Y6P08AA/AT	
	HP 256GB SATA SED OPAL2 SSD	Υ	Υ	G7U67AA	
	HP 512GB SATA SED OPAL2 SSD	Υ	Υ	N8T26AA	
	HP 240GB SATA Enterprise SSD	Υ	Υ	T3U07AA	
	HP 480GB SATA Enterprise SSD	Υ	Υ	T3U08AA	
	HP 960GB 2.5in Enterprise SATA-3 SSD	Υ	Υ	1W6P8AA	
	1920GB 2.5in Enterprise SATA-3 SSD	Υ	Υ	1W6P9AA	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	PCIe SSDs for HP Workstations				
	HP Z Turbo Drive 256GB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD56AA	4
	HP Z Turbo Drive 512GB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD57AA/AT	4
	HP Z Turbo Drive 1TB MLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD58AA	4
	HP Z Turbo Drive 256GB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD59AA/AT	
	HP Z Turbo Drive 512GB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD60AA	
	HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	1PD61AA	
	HP Z Turbo Drive 2TB TLC Z4/Z6 G4 SSD Kit	Υ	Υ	3KP39AA	
	HP Z Turbo Drive 256GB Z4/Z6 G4 SED Kit	N	N	EOL	4
	HP Z Turbo Drive 512GB Z4/Z6 G4 SED Kit	N	N	EOL	4
	HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SED Kit	Υ	Υ	6YT76AA	
	HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SED Module	Υ	Υ	6YT79AA	
	HP Z Turbo 2TB SED OPAL2 TLC M.2 Z4/Z6 SSD	Υ	Υ	2Y7W6AA	
	HP 256GB M.2 2280 PCIe NVMe TLC SSD Z2/Z4/Z6 Kit	Υ	Υ	8PE68AA	3
	HP 512GB M.2 2280 PCIe NVMe TLC SSD Z2/Z4/Z6 Kit	Υ	Υ	8PE69AA	3
	HP 1TB M.2 2280 PCIe NVMe TLC SSD Z2/Z4/Z6 Kit	Υ	Υ	8PE70AA	3
	HP 256GB M.2 2280 PCIe NVMe TLC SSD Module	N	Υ	8PE62AA	2
	HP 512GB M.2 2280 PCIe NVMe TLC SSD Module	N	Υ	8PE63AA	2
	HP 1TB M.2 2280 PCIe NVMe TLC SSD Z2 Module	N	Υ	8PE64AA	2
	HP 2TB PCIe NVME TLC M.2 Z4/6 G4 SSD	Υ	Υ	35F74AA	
	HP Z Turbo Drive Dual Pro				
	HP Z Turbo Drive Dual Pro 256GB TLC SSD	Υ	Υ	4YF60AA	3
	HP Z Turbo Drive Dual Pro 512GB TLC SSD	Υ	Υ	4YF61AA	3
	HP Z Turbo Drive Dual Pro 1TB TLC SSD	Υ	Υ	4YF62AA	3



Supported Components

HP Z Turbo Drive Dual Pro 2TB TLC SSD	Υ	Υ	4YF63AA	3
HP 256GB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	Υ	Υ	8PE74AA	3
HP 512GB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	Υ	Υ	8PE75AA	3
HP 1TB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	Υ	Υ	8PE76AA	3
HP Z Turbo Drive Quad Pro				
HP Z Turbo Drive Quad Pro 2x256GB PCle TLC SSD	Υ	Υ	4YZ38AA	1
HP Z Turbo Drive Quad Pro 2x512GB PCle TLC SSD	Υ	Υ	4YZ39AA	1
HP Z Turbo Drive Quad Pro 2x1TB PCIe TLC SSD	Υ	Υ	4YZ40AA	1
HP Z Turbo Drive Quad Pro 2x2TB PCIe TLC SSD	Υ	Υ	3KP42AA	
HP Z Turbo Drive Quad Pro 256GB SSD module	N	Υ	N2N00AA	2
HP Z Turbo Drive Quad Pro 512GB SSD module	N	Υ	N2N01AA	2
HP Z Turbo Drive Quad Pro 1TB SSD module	N	Υ	T9J00AA	2
HP Z Turbo Drive Quad Pro 2TB SSD module	N	Υ	3KP43AA	
Intel® 905p Series SSD (Optane SSD)				
Intel® Optane SSD 905p 280GB AiC**	Υ	Υ	2SC47AA	
Intel® Optane SSD 905p 480GB AiC**	Υ	Υ	2SC48AA	
Intel® Optane SSD 905p 380GB M.2 SSD Module	Υ	Υ	6LA66AA	

Note 1: Dual M.2 SSD modules plus carrier and heat sink
Note 2: M.2 SSD module only, for Quad Pro or Dual Pro carrier

Note 3: Single M.2 SSD module plus dual carrier and heat sink

Note 4: These M.2 SSD kits and module are End of Life and no longer available.

^{**} PCIe card installed in standard PCIe x4 slot

Hard Drive Controllers		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SAS Controller				
	MicroSemi SmartHBA2100-4i4e SAS Controller	Υ	Υ	1FV90AA	

Graphics

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported # of cards
Graphics Cable Adapters					
HP DisplayPort to VGA Adapter	Υ	Υ	AS615AA		
HP DisplayPort to HDMI Adapter	Υ	Υ	K2K92AA		
HP DisplayPort to Dual Link DVI Adapter	Υ	Υ	NR078AA		1
HP DisplayPort to DVI-D Adapter	Υ	Υ	FH973AA		1
HP DisplayPort to DVI-D Adapter (2-pack)	Υ	N			1
HP DisplayPort to DVI-D Adapter (4-pack)	Υ	N			1
HP DisplayPort to DVI-D Adapter (6-pack)	Υ	N			1
NVIDIA® SLI 3-slot Graphics Connector	Υ	Υ	2YY85AA		1



Supported Components

Quadro RTX NVLink High-Bandwidth 3-slotBridge (RTX 8000, RTX 6000)	N	Υ	6FY13AA	2
Quadro RTX NVLink 3-slotBridge (RTX 5000)	Υ	Υ	6FY14AA	2
NVIDIA NVLink 3 Slot Bridge (RTX A6000, RTX A5000)	Υ	Υ	340L3AA	2
Entry 3D				
NVIDIA® Quadro® P620 2GB Graphics	Υ	Υ	3ME25AA	2
NVIDIA® T400 4 GB 3mDP Graphics	Υ	Υ	5Z7EOAA/AT	2
Mid-range 3D				
NVIDIA® T1000 4 GB 4mDP Graphics	Υ	Υ	20X22AA/AT	2
NVIDIA® T1000 8 GB 4mDP Graphics	Υ	Υ	5Z7D8AA	2
NVIDIA® Quadro® P1000 4GB Graphics	Υ	Υ	1ME01AA	3
NVIDIA RTX A2000 6 GB 4mDP Graphics	Υ	Υ	340L0AA	3
NVIDIA RTX A2000 12 GB 4mDP Graphics	Υ	Υ	5Z7D9AA	2
AMD Radeon™ Pro WX 3200 4GB Graphics	Υ	Υ	6YT68AA	2
AMD Radeon Pro W6600 8 GB GDDR6 4DP Graphics	Υ	Υ	340K5AA	1
High End 3D				
NVIDIA® RTX A4500 20 GB GDDR6 4DP Graphics	Υ	Υ	5S458AA/AT	2
AMD Radeon™ Pro W5500 8GB Graphics	Υ	Υ	9GC16AA/AT	2
AMD Radeon™ Pro W5700 8GB Graphics	Υ	Υ	9GC15AA/AT	1
Ultra High-End 3D				
NVIDIA Long-Life RTX A4000E 16 GB 4DP Graphics	N	Υ	6H7J7AA	1
NVIDIA® RTX A5000 24 GB Graphics	Υ	Υ	20X23AA	2
NVIDIA® RTX A6000 48 GB 4DP Graphics	Υ	Υ	2S6U3AA	1
AMD Radeon Pro W6800 32 GB Graphics	Υ	Υ	340K7AA	1
NVIDIA® Quadro® Sync II	Υ	Υ	1WT20AA	

Memory		SL Processor	CL Processor	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
1	DDR4-2666 ECC Registered DIMMs						
:	8GB (1x8GB) DDR4-2666 ECC Reg Memory	Υ	N	Υ	Υ	1XD84AA	1,2
•	16GB (1x16GB) DDR4-2666 ECC Reg Memory	Υ	N	N	Υ	1XD85AA	1,2
:	32GB (1x32GB) DDR4-2666 ECC Reg Memory	Υ	N	N	Υ	1XD86AA	1,2
1	DDR4-2933 ECC Registered DIMMs						
:	8GB (1x8GB) DDR4-2933 ECC Reg Memory	Υ	Υ	Υ	Υ	5YZ56AA	1,2
•	16GB (1x16GB) DDR4-2933 ECC Reg Memory	N	Υ	N	Υ	5YZ54AA	1,2
	32GB (1x32GB) DDR4-2933 ECC Reg Memory	N	Υ	N	Υ	5YZ55AA	1,2
(64GB (1x64GB) DDR4-2399 ECC Reg Memory	N	Υ	N	Υ	5YZ57AA	1,2

SL Processor: Are processors formerly known as Intel® Skylake that are sold under the model name Intel® Xeon® SP: Platinum 8100, Gold 6100, Gold 5100, Silver 4100 and Bronze 3100 Family



Supported Components

CL Processor: Are processors formerly known as Intel® Cascade Lake that are sold under the model name Intel® Xeon® SP: Platinum 8200, Gold 6200, Gold 5200, Silver 4200 and Bronze 3200 Family

NOTES:

1: For details on the supported memory configurations on the HP Z6 G4 Workstation, please refer to the System Technical Specifications - System Board section of this document.

Each processor supports up to 6 channels of DDR4 memory. To realize full performance at least 1 DIMM must be inserted into each channel.

With single-processor configurations, 6 DIMM slots are available. 6 additional DIMM slots are available with the 2nd CPU & Memory Module.

The CPUs determine the speed at which the memory is clocked. If a 2400MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2400MT/s, regardless of the specified speed of the memory.

The Z6 G4 is designed to work ONLY with DDR4 memory. The system will not work with DDR3 memory.

2: Z6 G4 configurations that include a 2nd CPU require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA). Z6 G4 configurations that include greater than 32GB total system memory require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA).

NOTE: Factory-configured CTO (xxxxxAV) and aftermarket AMO (xxxxxAA, xxxxxAT) HP memory part numbers designated as "2666" may ship with "2933" or "3200" speed memory components. Similarly, HP Memory part numbers designated as "2933" may ship with "3200" speed memory. This does not affect HP part number availability, nor does it affect system performance or operation. All hardware configurations currently supporting HP memory part numbers designated as "2666" or 2933 have been fully qualified to work with fast speed memory and are fully supported by HP under standard support terms.

NVDIMM Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Optane™ DC Persistent Memory (DCPMM)				
	128GB (1x128GB) DC Persistent Memory Module	Υ	Υ	9NH78AA	1
	256GB (2x128GB) DC Persistent Memory Configuration	Υ	N		1
	512GB (4x128GB) DC Persistent Memory Configuration	Υ	N		1,2

NOTE 1: Supported only with Xeon 82xx, 62xx, 52xx and 4215/4215R processors.

- a. Available as factory configured in Memory Mode or Storage Mode.
- b. Systems configured with DCPMM memory will operate the memory subsystem at 2666 MT/s.
- c. Operating System Support:
 - i. Windows 11 Pro for Workstations with all updates applied
 - ii. Windows 10 Pro for Workstations v1903 or later with all updates applied.
 - iii. Linux OS support may be found in the Linux Hardware Support Matrix.
- d. Detailed setup, security and support information may be found in the Intel® Optane™ DC Persistent Memory: Configuration and Setup on HP Z6 G4 and Z8 G4 Workstation_white paper.
- e. DCPMM solutions require additional DRAM memory to be included in the solution:
 - i. Systems configured with DCPMM in Memory Mode will include DRAM memory to be used as cache. The amount of included DRAM memory is based on an 8:1 DCPMM to DRAM capacity ratio.
 - Systems configured with DCPMM in Storage Mode will require DRAM System Memory to be ordered separately.
 - iii. DCPMM Memory will report approximately 2% less than advertised capacity.
- f. Total Memory (DCPMM + DRAM) per processor must be <= 1TB or 2TB per dual processor system.
 - i. When configured in memory mode, additional DRAM does not count against maximum processor memory.



Supported Components

- g. Maximum number of DCPMM modules in a Z6G4 is 4 per processor.
- h. Customer is responsible for additional required DRAM when adding DCPMM modules in Memory Mode.
- i. HP Z6G4 configured with some AMD Graphics are limited to 1TB of total DCPMM and DRAM memory. See AMD Graphics specifications for details.

NOTE 2: Requires 2nd processor option.

Multimedia and Audio Devices



Supported Components

Multimedia and Audio Devices

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Realtek HD ALC221 Audio	Υ	N		

Optical and Removable Storage

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP SlimTray Optical Drives				
HP 9.5mm Slim Blu Ray Disc Writer	Υ	Υ	K3R65AA	1
HP 9.5mm Slim DVD ROM	Υ	Υ	K3R63AA	1
HP 9.5mm Slim DVD Writer	Υ	Υ	K3R64AA	1
HP Half Height Optical Drives				
HP HH DVD Writer (16X RW DVD-R)	N	Υ	4AR67AA	
HP SD Card Reader				
HP SD 4 Card Reader	Υ	Υ	Y0L99AA	
HDD Frame/Carriers				
HP DX175 Removable HDD Carrier	N	Υ	1ZX72AA	
HP DX175 Removable HDD Frame/Carrier	N	Υ	1ZX71AA	
NVMe Frame/Carrier				
HP QX310 Removable NVMe Frame/Carrier w/PCIe card	Υ	N	8GQ89AA/AT	
HP QX310 Removable Carrier only	N	Υ	8GQ91AA/AT	

NOTE 1: Installing an optical drive into Z6 G4 requires a 5.25" external bay adapter 746536-001 which is included in the ODD kit.

Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications

	Factory Configure d	Option Kit	Option Kit Part Number	Support Notes
NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Υ	Υ	436M8AA	1
HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	N	Υ	860T8AA	
HP 25GbE SFP28 LC Fiber Optic Transceiver	N	Υ	860T9AA	



Supported Components

HP i350-T2 PCIe Dual Port Gigabit NIC	Υ	Υ	V4A91AA	
Intel® i350-T4 PCIe 4-Port Gigabit NIC	N	Υ	W8X25AA	
Intel® Ethernet I210-T1 PCIe x1 Gb NIC	Υ	Υ	E0X95AA	
Aquantia® NBASE-T 5GbE PCIe NIC	N	Υ	1PM63AA	
HP Dual Port 10GBase-T NIC Module	Υ	Υ	1QL49AA	
Intel® 8265 802.11 a/b/g/n/ac + BT PCIe WLAN	N	Υ	1QL48AA	
Intel® X550-T2 10GbE Dual Port NIC	Υ	Υ	1QL46AA	
Intel® X710-DA2 10GbE SFP+ Dual Port NIC	Υ	Υ	1QL47AA	2
HP 10GbE SFP+ SR 1st Transceiver	Υ	Υ	C3N53AA	
HP 10GbE SFP+ SR 2 nd Transceiver	Υ	Υ	C3N53AA	
Intel® Wi-Fi 6 AX200 & BT PCIe	N	Υ	7CE01AA	2
Intel AX210 Wi-Fi 6e non-vPro +Bluetooth 5.2 External Antenna WLAN	N	Υ	340L7AA	
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Υ	Υ	1C7Q2AA	
Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT	

Note 1: Transceivers sold separately. You must have a transceiver installed in order to connect this card to a network.

Note 2: Windows 7 is NOT supported

Racking and Physical Security



Supported Components

Racking and Physical Security

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Z4/Z6 Side Panel Barrel Keylock	Υ	N		
HP Solenoid Lock / Hood Sensor	Υ	N		
HP Z4/Z6 Depth Adjustable Fixed Rail Rack Kit	N	Υ	2HW42AA	
HP Z2 Mini/Z2 TWR/Z4/Z6 Dept Adj Fixed Rail Rack Kit		Υ	2A8Y5AA	
HP Keyed Cable Lock 10mm	N	Υ	T1A62AA	

Input Devices

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	Υ	Υ	N3R88AA	
Business Slim PS/2 Wired Keyboard	Υ	Υ	N3R86AA	
USB Business Slim Wired Keyboard	Υ	Υ	N3R87AA	
USB Premium Wired Keyboard	Υ	Υ	Z9N40AA	
USB Wired SmartCard CCID Keyboard	Υ	Υ	E6D77AA	
HP 320K Wired Keyboard	Υ	Υ	9SR37AA	
HP Optical USB Mouse	Υ	Υ	QY777AA	
HP PS/2 Mouse	Υ	Υ	QY775AA	
HP USB Hardened Mouse	Υ	Υ	P1N77AA	
HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA	
HP Wired 320M Mouse	Υ	Υ	9VA80AA	

Other Hardware

	Factory		Option Kit Part	
	Configured	Option Kit	Number	Support Notes
HP ENERGY STAR® Certified Configuration	Υ			
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	Υ	Υ	1XM32AA	
HP Z6 G4 Memory Cooling Solution	Υ	Υ	2HW44AA	Note 1
HP Internal USB Port Kit	N	Υ	EM165AA	Note 2
HP eSATA 2 port PCI Bulkhead Kit	Υ	Υ	GM110AA	
HP Workstation Mouse Pad	Υ			
HP Remote System Controller	N	Υ	7K6D7AA	Note 3
HP Remote System Controller Main Board Adapter	N	Υ	7K6D8AA	
HP Integrated Remote System Controller	N	Υ	7K6D9AA	Note 3
HP Z4/Z6/Z8 G4 / ZCentral 4R Remote System Controller Cable Adapter	N	Y	7K6E5AA	Note 4
HP Remote System Controller for Universal KVM	N	Υ	7K7N2AA	

Supported Components

Note 1: Z6 G4 configurations that include a 2nd CPU require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA). Z6 G4 configurations that include greater than 32GB total system memory require the HP Z6 Memory Cooling Solution, which is available both CTO (2JA81AV) and AMO (2HW44AA).

Note 2: The HP Internal USB Port kit has a single USB 2.0 type A connector.

Note 3: Requires additional purchase of 7K6E5AA HP Z4/Z6/Z8 G4 / ZCentral 4R Remote System Controller Cable Adapter.

Note 4: By installing the HP Z4/Z6/Z8 G4 / ZCentral 4R Remote System Controller Cable Adapter (7K6E5AA), power will be stolen from the front USB ports on the host. This was necessary to be able to power the Remote System Controllers in all power states, and it leaves the front USB ports unpowered and unusable.

Application Software		Factory Configured		Option Kit Part Number	Support Notes
	Sobey Video Editing SW	Υ	N		
	HP ZCentral Remote Boost	N	N		
	Data Science Stack	Υ	N		1, 2
	WSL2/Ubuntu Data Science Stack	Υ	N		1, 3

*Not all Application Software for Z Desktop Workstations is included with purchase.

Note 1: Only available with NVIDIA graphics cards selections.

Note 2: Only available with Ubuntu 20.04 LTS preinstall.

Note 3: Only available with Windows 10 Pro for Workstations or Windows 11 Pro for Workstations.



Supported Components

Operating Systems

Windows 11 Pro for Workstations
Note 4,1
Windows 10 Pro for Workstations
Note 3,4,1
Ubuntu 20.04 LTS
Note 2
HP Linux® Installer Kit
Note 2
Red Hat® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)
Note 2,5

NOTE 1: Available with Windows Subsystem for Linux® (WSL2). **NOTE 2**: For detailed Linux® OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix

NOTE 3: Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

NOTE 4: Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

NOTE 5: This second OS must be ordered with the HP Linux® Installer Kit as the first OS.



System Technical Specifications

System Board

System Board Form Main System Board: Factor 24 x 31 cm

9.6 x 12.2 inches

2nd CPU/Memory Board (optional):

14.9 x 29.2 cm 5.85 x 11.50 inches

Processor Socket FCLGA3647 (Socket P)

1st CPU on system board

2nd CPU on optional 2nd CPU/Memory Module

CPU Bus Speed UPI: Up to 10.4GT/second, depending on processor

Chipset Intel® C622 Chipset **Super I/O Controller** Nuvoton SIO15

Memory Expansion

Memory Expansion Slots

DDR4 R-DIMM (Registered), ECC: 8GB, 16GB, 32GB, and 64GB

6 on system board (CPU0) + 6 on optional 2nd CPU/Memory Module (CPU1)

Memory Type Supported

Memory Modes NUMA (Non-Uniform Memory Architecture), Memory Node Interleave

2133MT/s, 2400MHz, 2666MT/s, and 2933MT/s

Memory Speed

Supported

Available Memory Configurations:

	Single Processor						
_	•	Top Slots		В	ottom Slo	ts	
Capacity	DIMM1	DIMM2	DIMM3	DIMM4	DIMM5	DIMM6	Perf Rating
8 GB	8 GB						Fair
16 GB	8 GB					8 GB	Good
24 GB	8 GB	8 GB	8 GB				Better
32 GB	8 GB		8 GB	8 GB		8 GB	Better
32 UD	16 GB					16 GB	Good
48 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	Best
40 UD	16 GB	16 GB	16 GB				Better
64 GB	16 GB		16 GB	16 GB		16 GB	Better
04 UD	32 GB					32 GB	Good
96 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	Best
90 UD	32 GB	32 GB	32 GB				Better
128 GB	32 GB		32 GB	32 GB		32 GB	Better
192 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	Best
256 GB	64 GB		64 GB	64 GB		64 GB	Better
384 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	Best

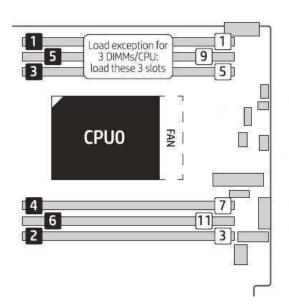
System Technical Specifications

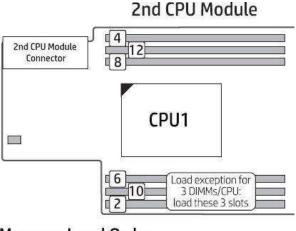
		Dual Processor											
			СР	U O					СР	U 1			
	1	op Slot	S	Во	ttom Sl	ots	7	Top Slot	S	Во	ttom Sl	ots	
Capacity	DIMM 1	DIMM 2	DIMM 3	DIMM 4	DIMM 5	DIMM 6	DIMM 1	DIMM 2	DIMM 3	DIMM 4	DIMM 5	DIMM 6	Rating
16 GB	8 GB						8 GB						Fair
32 GB	8 GB					8 GB	8 GB					8 GB	Good
48 GB	8 GB	8 GB	8 GB				8 GB	8 GB	8 GB				Better
64 GB	8 GB		8 GB	8 GB		8 GB	8 GB		8 GB	8 GB		8 GB	Better
04 UD	16 GB					16 GB	16 GB					16 GB	Good
96 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	8 GB	Best
90 UD	16 GB	16 GB	16 GB				16 GB	16 GB	16 GB				Better
128 GB	16 GB		16 GB	16 GB		16 GB	16 GB		16 GB	16 GB		16 GB	Better
128 UD	32 GB					32 GB	32 GB					32 GB	Good
192 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	16 GB	Best
192 UD	32 GB	32 GB	32 GB				32 GB	32 GB	32 GB				Better
256 GB	32 GB		32 GB	32 GB		32 GB	32 GB		32 GB	32 GB		32 GB	Better
230 UD	64 GB					64 GB	64 GB					64 GB	Best
204 CP	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	32 GB	Better
384 GB	64 GB	64 GB	64 GB				64 GB	64 GB	64 GB				Best
512 GB	64 GB		64 GB	64 GB		64 GB	64 GB		64 GB	64 GB		64 GB	Fair
768 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	64 GB	Good



Memory Loading Order:

Load Order for Single and Dual Processor Configuration





Memory Load Order



Maximum Memory

Supports up to 768 GB DDR4-2933 ECC RAM* (transfer rates up to 2933MT/s) and 384 GB DDR4-2666 ECC RAM (transfer rates up to 2666MT/s).

Memory Configuration (Supported)

- Only Registered ECC DIMMs are supported.
- Do not install memory modules into memory slots if corresponding processor is not installed.
- Dual processor configurations with memory modules installed for only one processor is not supported.

Notes

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

*768 GB configuration requires 2 CPUs configuration.

NVDIMM Memory

Intel® Optane™ DC Persistent Memory is available factory configured in the following capacities:

- 128GB (1x128GB) Single Processor Configuration
- 256GB (2x128GB) Single Processor Configuration
- 512GB (4x128GB) Dual Processor Configuration

NOTES:

- a. Supported only with Xeon 82xx, 62xx, 52xx and 4215/4215R processors.
- b. Available as factory configured in Memory Mode or Storage Mode.
- c. Systems configured with DCPMM memory will operate the memory subsystem at 2666 MT/s.
- d. Operating System Support:
 - i. Windows 11 Pro for Workstations with all updates applied.
 - ii. Windows 10 Pro for Workstations v1903 or later with all updates applied.
 - iii. Linux OS support may be found in the Linux Hardware Support Matrix.
- e. Detailed setup, security and support information may be found in the Intel® Optane™ DC Persistent Memory: Configuration and Setup on HP Z6 G4 and Z8 G4 Workstation white paper.
- f. DCPMM solutions require additional DRAM memory to be included in the solution:



System Technical Specifications

- i. Systems configured with DCPMM in Memory Mode will include DRAM memory to be used as cache. The amount of included DRAM memory is based on an 8:1 DCPMM to DRAM capacity
- ii. Systems configured with DCPMM in Storage Mode will require DRAM System Memory to be ordered separately.
- iii. DCPMM Memory will report approximately 2% less than advertised capacity.
- Total Memory (DCPMM + DRAM) per processor must be <= 1TB or 2TB per dual processor system.
 - i. When Configured in Memory Mode, additional DRAM does not count against maximum processor memory.
 - ii. Maximum number of DCPMM modules in a Z6G4 is 4 per processor.
- h. Customer is responsible for additional required DRAM when adding DCPMM modules in Memory Mode.
- HP Z6G4 configured with some AMD Graphics are limited to 1TB of total DCPMM and DRAM memory. See AMD Graphics specifications for details.

PCI Express Connectors Slot 0:

Mechanical-only, for use with devices that require only rear bulkhead mounting or when 2nd CPU riser is installed

Slot 1:

PCI Express Gen3 x4 - CPU with open-ended connector*

Slot 2:

PCI Express Gen3 x16 - CPU

Slot 3:

PCI Express Gen3 x4 - PCH with open-ended connector*

Slot 4:

PCI Express Gen3 x8 – CPU with open-ended connector (slot converts to x4 electrical when SSD is installed in 2nd M.2 slot)*

Slot 5:

PCI Express Gen3 x16 - CPU

Slot 6:

PCI Express Gen3 x4 - PCH with open-ended connector*

M.2 Slot 1:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

M.2 Slot 2:

M.2 PCIe Gen 3 x4 - CPU up to 80mm storage devices

* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.

Supported Drive Interfaces

6 SATA @6Gb/s, supports RAID 0, 1, 5, & 10 SATA

Serial Attached SCSI Requires Optional PCIe card

Factory Configured

RAID SATA RAID 1 Mirrored Array

SATA RAID 10 Striped/Mirrored



SATA RAID 0 Striped Array

Notes:

Factory integrated Intel® SATA RAID is Microsoft Windows only.

External SATA (eSATA) Supported on all SATA ports configurable with optional eSATA* cable kit

* hot plug / hot swap not supported with eSATA

Network Controller Integrated Intel®

I219LM GbE LAN

Supports the following management functionalities: Intel® AMT11.2, TXT, DASH

1.1, WOL, VLAN, and PXE 2.1

for 1GbE

Integrated Intel X722 Data rates supported: 1000 Mb/s

Compliance IEEE 802.1as/1588v2, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az,

802.3x

Up to 16 UDP/TCP programmable filters

Bus architecture: PCIe 3.0 **UEFI and PXE Boot ROM support** Intel iWARP Support (RDMA) Network transfer rates:

1000BASE-T (full-duplex) 2000 Mb/s

Management capabilities: WOL (Excluding Max Power Savings), auto MDI

crossover, PXE, Quad Hash filtering, RSS, Advanced cable

diagnostics

USB Connector(s) Front I/O Entry: 4 USB 3.1 Gen1 (Left-most Port has Charging Capability) Front

Front I/O Premium: 2x USB 3.1 Gen1, 2x USB 3.1 Gen2 Type-C™ (Left-most Port

has Charging Capability)

Charging Ports provide 1.5 Amps @ 5 Volts

Standard USB Type A Ports provide 900mA @ 5 Volts

USB Type C Ports provide 3 Amps @ 5 Volts and adhere to the Power

Delivery 3.0 specification.

Rear 6 USB 3.1 G1 Type A

Internal 1 USB 3.1 G1 single-port header

> 1 USB 2.0 single-port header 1x USB 2.0 dual-port header

Integrated Graphics

No

HD Integrated Audio Realtek ALC221

Flash ROM Yes

One for each CPU socket **CPU Fan Header**

Rear Chassis Fan Header Yes Front PCI Fan Header Yes CMOS Battery Holder -Yes

Lithium

Integrated Trusted

Platform Module

Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified FIPS 140-2 Certified (firmware v7.85)

TPM Certified products list:

https://trustedcomputinggroup.org/membership/certification/tpm-certifiedproducts/

Power Supply Headers Power Switch, Power

Yes Yes

LED & Hard Drive LED

Header

System Technical Specifications

Clear Password Jumper Yes

Serial Port 1 internal header

Parallel Port No

Kevboard/Mouse USB or PS/2

Hood Lock Header Yes **Hood Sensor Header** Yes

Memory Fan 1 Memory Fan Header per CPU

AUX IN (audio)

Z6 Required Power Supply Info

1000W 90% Efficient, Custom PSU **Power Supply** (Wide Ranging, Active PFC)

90-269 VAC **Operating Voltage Range**

100-127 VAC 118 VAC **Rated Voltage Range** 200-240 VAC

Rated Line Frequency 50-60 Hz 400 Hz **Operating Line Frequency Range** 47-66 Hz 393-407 Hz

12 A @ 100-127 VAC 12A @ 118 VAC **Rated Input Current**

6.3 A @ 200-240 VAC

Typical = 2467 btu/hr **Heat Dissipation** Maximum = 4112 btu/hr (Configuration and software dependent)

80x25 mm variable speed **Power Supply Fan ENERGY STAR® Qualified**

Yes

(Configuration dependent)

80 PLUS® Compliant

(Instantly Available PC)

Yes, 90% Efficient The Z6 G4 1000W power supply efficiency report can be found at this link:

> https://plugloadsolutions.com/psu reports/HP D15-1K0P1A_1000W_ECOS%204838_Report.pdf

FEMP Standby Power Compliant @115V Yes

(<1W in S5 – Power Off) EuP Compliant @ 230V Yes

(<0.5 W in S5 - Power Off) **CECP Compliant @ 220V** Yes; Configuration dependent (<4W in S3 - Suspend to RAM)

Power Consumption in sleep mode

(as defined by ENERGY STAR®) – Suspend to RAM <= 20W

(S3)

Yes **Built-in Self Test LED**

Surge Tolerant Full Ranging Power Supply Yes (withstands power surges up to 2000V)

Sensor Header Integrated in Front User Interface (Power Switch, Power LED, HDD LED.

Speaker) Cable

Integrated Gigabit Ethernet Integrated Intel® I219LM GbE LAN

Clear CMOS Button Yes

System Technical Specifications

System Configuration

Example Z6 G4	Processor	1x Intel Xeon	x Intel Xeon 3104 (Six-core)							
Configuration #1	Memory	1x 8GB DDR4-	-2666 (Register	ed DIMM)						
•	Graphics	1x NVIDIA Qua	adro P400							
	Disks / Optical	1x 500GB SATA 7200 ; 1x Slim DVD-ROM SATA								
	Power Supply	1000W 90% c	ustom PSU							
	Other	NA								
		115	5 VAC	230	VAC	100	VAC			
Energy Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled			
	Windows Idle (S0)	54	.109	54.	586	54.	906			
•	Windows Busy Typ(S0)	94.256		94.275		94.043				
	Windows Busy Max (S0)	95.992		95.268		95.643				
	Sleep (S3)	6.219	6.205	6.319	6.306	6.334	6.239			
	Off (S5)	3.354	3.343	3.521	3.341	3.350	3.342			
	Zero Power Mode (ErP)	0.209		0.388		0.195				
		115	5 VAC	230	VAC	100	VAC			
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled			
(Btu/hr)	Windows Idle (S0)	184	1.619	186.247		187.339				
	Windows Busy Typ(S0)	321	1.601	321	.666	320.875				
	Windows Busy Max (S0)	327	7.524	325	.054	326.334				
	Sleep (S3)	21.219	21.171	21.561	21.516	21.611	21.287			
	Off (S5)	11.444	11.406	12.014	11.399	11.430	11.403			
	Zero Power Mode (ErP)	0.	0.713		1.323		0.665			

Example Z6 G4	Processor	1x Intel Xeon	4108 (Eight-co	re)					
Configuration #2	Memory	4x 8GB DDR4-2666 (Registered DIMM)							
	Graphics	1x NVIDIA Quadro P2000							
	Disks / Optical	2x 1TB SATA 7200 ; 1x Slim DVDRW SATA							
	Power Supply	1000W 90% c	ustom PSU						
	Other	NA							
Energy Consumption		115	5 VAC	230	VAC	100 VAC			
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled		
	Windows Idle (S0)	61.661		61.531		61.354			
	Windows Busy Typ(S0)	168.665		167.375		166	.535		
•	Windows Busy Max (S0)	166.097		163.682		169.674			
	Sleep (S3)	7.231	7.177	7.229	7.217	7.324	7.248		
•	Off (S5)	3.376	3.366	3.527	3.512	3.354	3.350		
	Zero Power Mode (ErP)	0.	211	0.3	886	0.195			
		115	5 VAC	230	VAC	100	VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	210.387		209.944		209.340			



System Technical Specifications

Windows Busy Typ(S0)	575.485		571.084		568.217	
Windows Busy Max (S0)	576.959		575.543		578.928	
Sleep (S3)	24.672	24.488	24.665	24.624	24.989	24.730
Off (S5)	11.519	11.484	12.034	11.983	11.443	11.430
Zero Power Mode (ErP)	0.	720	1.3	17	0.6	665

Example Z6 G4	Processor	1x Intel Xeon	6136 (Twelve-c	ore)					
Configuration #3	Memory	6x 8GB DDR4-2666 (Registered DIMM)							
ENERGY STAR	Graphics	1x NVIDIA Qua	adroP4000						
QUALIFIED	Disks/Optical	2x 1TB SATA	7200 ; 1x Slim D	VDRW SATA					
	Power Supply	1000W 90% c	ustom PSU						
	Other	NA							
Energy Consumption		115	5 VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled		
	Windows Idle (S0)	79	.074	79.109		79.938			
	Windows Busy Typ(S0)	324.975		317.991		327.451			
	Windows Busy Max (S0)	328.268		320.296		329.668			
	Sleep (S3)	7.847	7.756	7.878	7.826	7.931	7.852		
	Off (S5)	3.353	3.348	3.535	3.489	3.373	3.355		
	Zero Power Mode (ErP)	0.206		0.386		0.196			
		115	5 VAC	230	VAC	100	VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	269	9.801	269.920		272.748			
	Windows Busy Typ(S0)	110	8.815	1084	1.985	1117	7.262		
	Windows Busy Max (S0)	112	0.051	1092	2.850	1124.827			
	Sleep (S3)	26.774	26.463	26.880	26.702	27.061	26.791		
	Off (S5)	11.441	11.426	12.061	11.904	11.509	11.447		
	Zero Power Mode (ErP)	0.	703	1.3	317	0.6	69		

Example Z6 G4	Processor	2x Intel Xeon	8160 (Dual 24	1-core)						
Configuration #4	Memory	12x 32GB DDR4-2666 (Registered DIMM)								
	Graphics	2x NVIDIA Qua	2x NVIDIA Quadro P5000							
	Disks / Optical	4x 2TB SATA 7	4x 2TB SATA 7200 ; 1x Slim DVDRW SATA							
	Power Supply	1000W 90% c	1000W 90% custom PSU							
	Other	NA								
Energy Consumption		115	VAC	230 VAC		100 VAC				
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled			
	Windows Idle (S0)	112.	388	115	.635	112	.102			
	Windows Busy Typ(S0)	512.	368	490	.165	526.905				
	Windows Busy Max (S0)	698.	548	673.465		706.461				
1	Sleep (S3)	14.208	13.833	14.698	14.487	15.176	13.886			



System Technical Specifications

	Off (S5)	3.511	3.418	3.575	3.570	3.509	3.412
	Zero Power Mode (ErP)	0.2	87	0.3	887	0.2	272
		115	VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	383.469		394.547		382.492	
	Windows Busy Typ(S0)	1748.120		1672.443		1797.800	
	Windows Busy Max (S0)	2383	.446	2297	7.863	2410).445
	Sleep (S3)	48.478	47.198	50.150	49.430	51.781	47.379
	Off (S5)	11.980	11.662	12.198	12.181	11.973	11.642
	Zero Power Mode (ErP)	0.9	79	1.3	321	0.9	28

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

DECLARED NOISE EMISSIONS

System Configura	tion
(Entry level)	

Processor Info	Intel® Xeon® Gold 6130 processor 2.1GHz 12C CPU
Memory Info	24GB (3x8GB) DDR4-2666 ECC Memory RDIMMs
Graphics Info	1-NVIDIA® Quadro® P400 2GB
Disks/Optical	1-500GB SATA 7200RPM 3.5" HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
Power Supply	1000 W

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.3	15
	Hard drive Operating (random reads)	3.5	18

System Configuration
(Mid-range)

Processor Info	Intel® Xeon® Platinum 8168 processor 2.7GHz 24C CPU
Memory Info	96GB (6x16GB) DDR4-2666 ECC Memory RDIMMs
Graphics Info	1-NVIDIA® Quadro® P6000 24GB
Disks/Optical	2-4TB 6Gb/s 7200RPM SATA HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
Power Supply	1000 W

		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.8	23
	Hard drive Operating (random reads)	3.9	23

System Technical Specifications

System Configuration (High end)	Processor Info	2-Intel® Xeon® Gold 6136 processor 3.0GHz 12C CPU	
	Memory Info	192GB (12x16GB) DDR4-2666 ECC Memory RDIMMs	
	Graphics Info	1-NVIDIA® Quadro® P6000 24GB	
	Disks/Optical	2-4TB 6Gb/s 7200RPM SATA HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer	
	Power Supply	1000 W	

		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.8	23
	Hard drive Operating (random reads)	3.9	24

ENVIRONMENTAL DATA

Environmental Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating: 3,048 m (10,000 feet)

> Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation

Non-operating: 9,144 m (30,000 feet)

Shock (non-repetitive) Operating: ½-sine: 40g, 2-3ms (~62 cm/sec)

Non-operating: 1/2-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20q

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g2/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information.

Tool-less, no carrier or rails required **Hard Drives** Tool-less

Optional 5.25" external bay carriers

Expansion Cards Tool-less

Processor Socket 1st socket on main system board. 2nd socket on optional 2nd CPU/Memory Module.

Blue User Touch Points Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

Optical Drive

System Technical Specifications

Memory Tool-less

System Board Torx T15 screws

2nd CPU/Memory Module: Tool-less

Dual Color Power/Failure LED = Yes Front of Computer LEDs

HDD Activity LED = Yes

Configuration Record SW Yes

Over-Temp Warning on

Yes, at POST screen on reboot

Screen

Restore CD/DVD Set **Dual Function Front** Yes, restores the computer to its original factory shipping image; can be obtained via HP Support.

Yes, also acts as a reset switch when held for 4 seconds.

Power Switch

Padlock Support Yes

Kensington Cable Lock (optional): Prevents entire system theft and system access. 3mm x 7mm slot at **Cable Lock Support**

rear of system

Universal Chassis Clamp

Lock Support

Solenoid Lock and Hood

Sensor

Access Panel Intrusion Sensor: Yes (optional).

Removable Media

Write/Boot Control

Yes, user can prevent the workstation from writing to or booting from removable media.

Access Panel Solenoid Lock: Yes (optional). Activated remotely to prevent system entry.

Power-On Password Yes, prevents an unauthorized person from booting up the workstation

Yes, prevents an unauthorized person from changing the workstation configuration **Setup Password**

3.3V Aux Power LED on

System PCA

Yes

NIC LEDs (integrated)

(Green & Amber)

Yes

CPUs and Heatsinks

CPU heatsink removal requires a T-30 Torx screwdriver.

Power Supply Diagnostic Yes

LED

Front Power Button Yes **Rear Power Button** Yes

Front Power LED Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

Front ODD Activity LED Yes on device

Internal Speaker Yes

System/Emergency ROM Recovers corrupted system BIOS.

Flash Recovery

Cooling Solutions Air cooled forced convection

Power Supply Fans 1 - 80 mm x 80 mm x 25 mm (non-serviceable)

CPU Heatsink Fan 1st CPU: 1 - 80mm

Optional 2nd CPU: 1 - 60mm x 25mm

Front memory fan: 1 - 80mm x 25mm **Memory Fan**

Memory duct blower: 1 - 90mm x 25mm 2nd CPU/Memory Module: 1 - 60mm x 25mm

Front chassis fan: 1 - 120mm x 25mm **Chassis Fans**

Rear chassis fan: 1 - 120mm x 25mm

HP Vision Diagnostics Offline Edition

HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot, and is

available as a download from HP Support.

Access Panel Key Lock ACPI-Ready Hardware

Yes, side panel barrel keylock (optional from the factory only) Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low-power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Integrated Infineon TPM 2.0. TCG and FIPS 140-2 Certified

Chip

Handles

Integrated Chassis

Yes, Front handle and dedicated rear recess

Power Supply

Requires T15 Torx or flat blade screwdriver

PCIe Card Retention Yes, tool-less

Rear (all)

Middle (full-height cards)

Front (full-length cards with extender)

Flash ROM Yes Diagnostic Power Switch Yes

LED on board

Clear Password Jumper Yes **Clear CMOS Button** Yes CMOS Battery Holder Yes **DIMM Connectors** Yes

BIOS

BIOS 32-bit Services

Standard BIOS 32-bit Service Directory Proposal v0.4

PCI 3.0 Support

Full BIOS support for PCI Express through industry standard interfaces.

ATAPI

ATAPI Removable Media Device BIOS Specification Version 1.0.

BBS

BIOS Boot Specification v1.01.

WMI Support

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On ROM Based Computer Users can define a specific date and time for the system to power on.

Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Replicated Setup

Flash Recovery with

Video

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

System Management BIOS 2.8, for system management information. **SMBIOS Boot Control** Disables the ability to boot from removable media on supported devices.

Recovers system BIOS in corrupted Flash ROM.

Memory Change Alert

Alerts management console if memory is removed or changed.



System Technical Specifications

Thermal Alert Monitors the temperature state within the chassis. Three modes:

NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console. **ACPI (Advanced** Allows the system to enter and resume from low power modes (sleep states).

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Management Interface) Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen. Ownership Tag

Shutdown

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC (Suspend to RAM - ACPI

sleep state S3)

Allows for very low power consumption with guick resume time.

Remote System Installation via F12 (PXE operating system.

2.1) (Remote Boot from Server)

Allows a new or existing system to boot over the network and download software, including the

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test) Auto Setup when new

hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory.

Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. **Per-slot Control** Control parameters are set according to detected hardware configuration for optimal acoustics. Adaptive Cooling (Pre-video) critical errors are reported via beeps and blinks on the power LED.

Pre-boot Diagnostics Industry Standard Specification Support

Industry Standard Revision Supported by the BIOS

UEFI Specification

Revision

Asset Tag

2.6

ACPI Advanced Configuration and Power Management Interface, Version 5.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7



PCI Express PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0

PMM POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified

FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification

SMBIOS System Management BIOS Reference Specification, Version 2.8

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

Eco-Label Certifications & This product is low halogen except for HP Z Turbo Quad Pro PCIe TLC SSD, CRU QX 428 & QX448 **Declarations** removable storage frames, ConnectX-6 DX Amphenol 10 & 25 Gb Transceivers, Intel VROC M.2 RAID

module, power cords, cables, and peripherals. Service parts obtained after purchase may not be Low Halogen.

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program
- The ECO declaration (TED)
- TCO Certified configurations available*

*TCO Certified configurations available when ENERGY STAR configurations are selected with a USB Type-C® connector. ENERGY STAR available with a combination of high-performance CPU's, high-performance GPU's and select memory configurations.

The Z6 G4 is registered EPEAT® Silver in the US and Canada. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party

option store for solar generator accessories at http://www.hp.com/go/options

The battery in this product complies with EU Directive 2006/66/EC

Battery mass: 3g

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight



Batteries

Lead greater than 40ppm by weight

Restricted Material Usage This product meets the material restrictions specified in HP's General Specification for the Environment.

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis

Low Halogen Statement

This product is low halogen except for power cords, external cables and peripherals. Service parts obtained after purchase may not be low halogen.

(NOTE: optional low-halogen power cables are available for some countries in Europe)

and Recycling

End-of-Life Management HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Sustainability Report

Eco-label certifications:

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificate:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment
 - (WEEE) Directive 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.

Packaging

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting
- A multi-unit eco packaging option is available to institutional customers that uses less packaging material or has a lower volume footprint than conventional single-unit packaging. Please contact your sales representative for additional details.

Packaging Materials

Internal **External** Cushions and plastic bags made of low density polyethylene (LDPE). Outer carton, accessories carton, and insert made of corrugated paper board.

Manageability

Industry Standard Specifications

This product meets the following industry standard specifications for manageability functionality:



DASH 1.1 (via Intel[®] LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 11.2x Technology (AMT)

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.2x includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- · Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel® vPro™ Technology The HP Z6 G4 Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor Scalable Family
- Intel® C622 chipset
- Intel® I219LM GbE LAN

Remote Manageability Software Solutions

The HP Z6 G4 Workstation is supported on the following remote manageability software consoles:

- LANDesk Management Suite (HP recommended solution)
- Microsoft System Center Configuration Manager
- HP Client Automation Enterprise

For questions or support for manageability needs, please visit

http://www.hp.com/go/clientmanagement

System Software Manager Service, Support, and Warranty For questions or support for SSM, please visit: http://www.hp.com/go/ssm

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.



System Technical Specifications

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at: http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Environmental Sustainability questions concerning:

Ecolabels (EPEAT, TCO, etc.)

ENERGY STAR, California Energy Commission (CEC)

Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
Product specific environmental features (material content, packaging content, recycled content, etc.)
China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)

GS Certificates

Product Safety Certificates (UL, CB, BIS, etc.)

EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)

CCC Certificates

Ergonomics

Please contact techregshelp@hp.com

Product Change Notification

Certification

and Compliance

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.



Stable & Consistent Offerings

Global Series SKUs	As part of its commitment to hardware so

ts commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this

section.

Droduct #

Stable & Consistent Offerings

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors

Product #	Ullering
2DL32AV	Intel® Xeon® Gold 6128 processor
2DL33AV, 1XM44AA	Intel® Xeon® Gold 6128 2 nd processor
2DL22AV	Intel® Xeon® Silver 4114 processor
2DL23AV, 1XM49AA	Intel® Xeon® Silver 4114 2nd processor
2DL18AV	Intel® Xeon® Silver 4108 processor
2DL19AV, 1XM51AA	Intel® Xeon® Silver 4108 2nd processor

Offering

Z5H22AV, LQ037AA 1TB SATA 7200 RPM 3.5" HDD 1TB 7200RPM SATA 3.5in 2nd Z5H23AV Z5H25AV 1TB 7200RPM SATA 3.5in 3rd Z5H24AV 1TB 7200RPM SATA 3.5in 4th

Graphics Offering Product # N/A

N/A

Product # Offering Memory N/A N/A

Optical and Removable Product # Offering Storage N/A N/A



Technical Specifications - Processors

Intel® Xeon® W-3200 Series CPU

Intel® Xeon® W-3265 2.7 2933 24C processor

Intel® Xeon® W-3245 3.2 2933 16C processor

Intel® Xeon® W-3225 3.7 2666 8C processor

Intel® Xeon® W-3223 3.5 2666 8C processor

Intel® Xeon® Scalable CPU

Intel® Xeon® Gold 6258R processor

Intel® Xeon® Gold 6248R processor

Intel® Xeon® Gold 6246R processor

Intel® Xeon® Gold 6244 processor

Intel® Xeon® Gold 6242R processor

Intel® Xeon® Gold 6242 processor

Intel® Xeon® Gold 6240 processor

Intel® Xeon® Gold 6234 processor

Intel® Xeon® Gold 6230R processor

Intel® Xeon® Gold 6226R processor

Intel® Xeon® Gold 6226 processor

Intel® Xeon® Gold 6136 processor

Intel® Xeon® Gold 6128 processor

Intel® Xeon® Gold 5222 processor

Intel® Xeon® Gold 5220R processor

Intel® Xeon® Gold 5218R processor

Intel® Xeon® Gold 5218 processor

Intel® Xeon® Gold 5118 processor

Intel® Xeon® Silver 4216 processor

Intel® Xeon® Silver 4215R processor

Intel® Xeon® Silver 4214R processor

Intel® Xeon® Silver 4214 processor

Intel® Xeon® Silver 4210R processor

Intel® Xeon® Silver 4210 processor

Intel® Xeon® Silver 4208 processor

Intel® Xeon® Silver 4114 processor

Intel® Xeon® Silver 4108 processor

Intel® Xeon® Bronze 3206R processor

Intel® Xeon® Bronze 3204 processor



STORAGE/HARD DRIVES

HP SAS (Serial Attached HP 300GB SAS 15K SFF SCSI) Hard Drives for HP HDD

Workstations

Capacity300GBHeight5.9 in; 15 cm

Width Media Diameter 3.5 in; 8.9 cm

Interface 12Gb/s SAS

Synchronous Transfer Up to 1200 MB/s (SAS single port)*

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, Average 2.0ms *

includes controller overhead, including

settling)

Rotational Speed 15K rpm

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

SATA (Serial ATA) Hard Drives for HP Workstations 500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity500GBHeight1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 16MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms*Average
Full Stroke11 ms*21 ms*

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 1TB

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Up to 600 MB/s*

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms*11 ms*
Full Stroke21 ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD CMR Capacity 2.0TB
Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Up to 600 MB/s*

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average1.0 ms*
11 ms*Full Stroke18 ms*

settling)

Rotational Speed 7,200 rpm



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Logical Blocks 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD SMR

Capacity 2.0TB 1 in; 2.54 cm Height

Width **Media Diameter** 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Up to 600 MB/s*

Buffer 64MB

Seek Time (typical reads, **Single Track** 1.2 ms* includes controller **Average** 12 ms* overhead, including **Full Stroke** 21 ms*

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 140° F (5° to 60° C)

3.0TB SATA 7200 rpm 6Gb/s 3.5" HDD

Capacity 3.0TB Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4.0 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 6.0 Gb/s*

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, **Single Track** 0.6 ms* includes controller 11 ms* **Average** overhead, including **Full Stroke** Not Specified* settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

YES

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer

Up to 600MB/s*

Seek Time (typical reads, includes controller overhead, including settling)

Single Track 0.32ms*

Average 7.45ms*

Full Stroke 14.2ms*

128MB

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*

Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

*Actual performance may vary.



Technical Specifications - Hard Drives

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 4TB

Height 0.275 in; 0.7 cm

Width Media Diameter 2.5 in; 6.36 cm

Physical Size 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s*

Buffer 128MB

Seek Time (typical reads,
includes controller
overhead, including
readsSingle Track
Average0.7ms*8.5ms*Full Stroke15.7ms*

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 140° F (0° to 60° C)

*Actual performance may vary.

500GB SATA 7.2K SED SFF HDD Capacity 500GB

Height 0.275 in; 0.7 cm

Width Media Diameter 2.5 in; 6.36 cm

Physical Size 2.75 in; 6.99 cm

InterfaceSerial ATA (6Gb/s)Synchronous TransferUp to 600MB/s*

Rate (Maximum)

Buffer 32MB

Seek Time (typical reads,
includes controller
overhead, including
cottling)Single Track
Average1ms*Average
Full Stroke4.2ms*25ms (typical)*

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 140° F (0° to 60° C)

*Actual performance may vary.

SATA SSDs for	HP
Workstations	

HP 256GB SATA 6Gb/s SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530MB/s (max)* **Sequential Write** 500MB/s (max)* **Random Read** 95K IOPS (max)* 83K IOPS (max)* **Random Write**

HP 256GB SATA 6Gb/s SED Opal 2 SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours 0.28 in; 0.7 cm Physical Size (Height) Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 530MB/s*

Sequential Write 500 MB/s* **Random Read** 95K IOPS* **Random Write** 83K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

HP 512GB SATA 6Gb/s

SSD

Capacity 512GB **Protocol SATA** 2.5" **Form Factor** Controller AHCI **NAND Type** 3D TLC

Endurance 388TBW (TB Written)

^{*}Actual performance may vary.

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Up to 550MB/s (Sequential Read)*

32° to 158° F (0° to 70° C)

Operating Temperature

Performance Sequential Read 530 MB/s*

> **Sequential Write** 500 MB/s* **Random Read** 95K IOPS* **Random Write** 83K IOPS*

HP 512GB SATA SED SSD

Capacity 512GB **Protocol SATA** 2.5" **Form Factor** Controller AHCI **NAND Type** 3D TLC

Endurance 388TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s Up to 600MB/s*

Synchronous Transfer

Operating Temperature

Rate (Maximum)

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530 MB/s*

Sequential Write 500 MB/s* **Random Read** 95K IOPS* **Random Write** 83K IOPS*

Up to 550MB/s (Sequential Read)*

Self-Encrypting Drive

Support

OPAL 1 and 2

*Actual performance may vary.

HP 1TB SATA 6Gb/s SSD

1TB Capacity **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)



^{*}Actual performance may vary.

Performance	Sequential Read	530 MB/s*	
	Sequential Write	500 MB/s*	
	Random Read	95K IOPS*	
	Random Write	83K IOPS*	

*Actual performance may vary.

HP 2TB SATA 6Gb/s SSD

Capacity2TBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s*

Sequential Write 500 MB/s *
Random Read 95K IOPS*
Random Write 83K IOPS*

*Actual performance may vary.

HP Enterprise Class 240GB SATA SSD

Capacity240GBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 2,200TBW (TB Written)

Reliability (MTTF)2.0M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterface6Gb/s SATASynchronous TransferUp to 600MB/s*

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance Sequential Read 540 MB/s*

Sequential Write 310 MB/s*
Random Read 93K IOPS*
Random Write 48K IOPS*

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP	Ent	erp	rise	Cla	SS
48	OGB	SAT	ΓA S	SD	

Capacity 480GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

4,400TBW (TB Written) **Endurance**

Reliability (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer**

Rate (Maximum)

Up to 600MB/s*

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 540 MB/s* **Sequential Write** 460 MB/s* **Random Read** 93K IOPS* **Random Write** 74K IOPS*

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection

Performance PCIe SSDs for HP Workstations

HP Z Turbo Drive 256GB M.2 2280 TLC SSD

Capacity 256GB PCle **Protocol** Form Factor M.2 Controller NVMe **NAND Type** 3D TLC **SED Support** Opal 2 **Endurance** 200TB Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s *

> **Sequential Write** 2200 MB/s * **Random Read** 240K IOPS * **Random Write** 480K IOPS *

HP ZTurbo Drive 512GB M.2 2280 TLC SSD

Capacity 512GB **PCIe Protocol Form Factor** M.2 **Controller** NVMe **NAND Type** 3D TLC **SED Support** Opal 2 **Endurance** 300TB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 2900 MB/s*
Random Read 460 K IOPS*
Random Write 500K IOPS*

HP ZTurbo Drive 1TB M.2 Capacity 2280 TLC SSD Protocol

Capacity 1TB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3 D TLC
SED Support Opal 2
Endurance 400TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s*
Random Read 580K IOPS*
Random Write 500K IOPS*

HP ZTurbo Drive 2TB M.2 Capacity 2280 TLC SSD Protocol

Capacity2TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3 D TLCSED SupportOpal 2Endurance500TBReliability (MTTF)1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

Sequential Write 2400 MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

HP Z Turbo Drive Quad Pro 2x256GB PCIe TLC SSD Capacity 512GB Protocol PCle

Form Factor PCIe Card, Full Height PCIe Slot



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Controller NVMe
NAND Type 3D TLC
SED Support Opal 2
Endurance 200TB
Reliability (MTBF) 1.5M hours

Interface PCIe Gen3 x4 architecture
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 2200 MB/s*
Random Read 240K IOPS*
Random Write 480K IOPS*

HP Z Turbo Drive Quad Pro 2x512GB PCIe TLC SSD

Capacity 1TB Protocol PCIe

Form Factor PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND Type3D TLCSED SupportOpal 2Endurance300TBReliability (MTBF)1.5M hours

InterfacePCIe Gen3 x4 architectureOperating Temperature32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*
Sequential Write 2900 MB/s*

Random Read 460 K IOPS*

Random Write 500K IOPS*

HP Z Turbo Drive Quad Pro Capacity 2x1TB PCIe TLC SSD Protocol

Capacity 2TB
Protocol PCIe

Form Factor PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND Type3D TLCSED SupportOpal 2Endurance400TB

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s*
Random Read 580K IOPS*
Random Write 500K IOPS*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

ΗP	Z	Tu	rbo	Drive	Dual
Pro	2	256	GB	SSD	

Capacity 256GB **Protocol** PCIe

Form Factor M.2 in Half-height, half-length card

Controller NVMe **NAND Type** 3D TLC

200TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

> **Sequential Write** 2200 MB/s* **Random Read** 240K IOPS* **Random Write** 480K IOPS*

HP Z Turbo Drive Dual Pro 512GB SSD

Capacity 512GB **Protocol** PCIe

Form Factor M.2 in Half-height, half-length card

Controller NVMe **NAND Type** 3D TLC

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

32° to 158° F (0° to 70° C) **Operating Temperature**

Performance Sequential Read 3500 MB/s*

Sequential Write 2900 MB/s* **Random Read** 460 K IOPS* **Random Write 500K IOPS***

HP Z Turbo Drive Dual Pro 1TB SSD

1TB Capacity **PCle Protocol**

Form Factor M.2 in Half-height, half-length card

Controller NVMe 3D TLC **NAND Type**

400TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s* **Random Read** 580K IOPS* **Random Write 500K IOPS***



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

HP Z Turbo	Drive	Dual
Pro 2TB SSI	D	

Capacity 2TB PCle **Protocol**

Form Factor M.2 in Half-height, half-length card

Controller **NAND Type** 3D TLC

Endurance 500TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

> **Sequential Write** 3000 MB/s * **Random Read 600K IOPS* Random Write 500K IOPS***

Mainstream PCIe SSDs for HP Workstations

HP 256GB M.2 2280 TLC

SSD

Capacity 256GB **Protocol** PCle **Form Factor** M.2 NVMe Controller 3D TLC **NAND Type** 200TB **Endurance** Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

32° to 158° F (0° to 70° C) **Operating Temperature**

Performance Sequential Read 3100 MB/s *

> **Sequential Write** 1400 MB/s * **Random Read** 200 K IOPS * **Random Write** 320 K IOPS *

HP 512GB M.2 2280 TLC

SSD

Capacity 512GB **Protocol** PCIe **Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC **Endurance** 300TB Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

32° to 158° F (0° to 70° C) **Operating Temperature**

Performance Sequential Read 3300 MB/s*

> **Sequential Write** 2500 MB/s* **Random Read** 225 K IOPS* **Random Write** 430 K IOPS*

*Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

HP 1TB M.2 2280 TLC SSD Capacity 1TB

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC
Endurance 400TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

Sequential Write 2500 MB/s*
Random Read 400 K IOPS*
Random Write 440 K IOPS*

HP 2TB M.2 2280 TLC SSD Capacity 2TB

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC
Endurance 500TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

Sequential Write 2700 MB/s*
Random Read 430 K IOPS*
Random Write 500 K IOPS*

Intel® 905p Series AIC PCIe SSD

Intel® 905p Series AIC 280GB PCIe SSD

Capacity 280GB Protocol PCIe

Form Factor PCIe Card, Half Height

Controller NVMe **NVM Type** 3DXPoint

Endurance 5.11 PBW (PB Written)

Reliability (MTBF) 1.6M hours

Operating Temperature 32° to 185° F (0° to 85° C)

Performance Sequential Read 2730 MB/s*

Sequential Write 2280 MB/s*
Random Read 587K IOPS*
Random Write 559K IOPS*

*Actual performance may vary.

Capacity 480GB

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Protocol PCIe

Form Factor PCIe Card, Half Height

Controller NVMe NVM Type 3DXPoint

Endurance 8.76 PBW (PB Written)

Reliability (MTBF) 1.6M hours

Operating Temperature 32° to 185° F (0° to 85° C)

Performance Sequential Read 2710 MB/s*

Sequential Write 2280 MB/s*
Random Read 582K IOPS*
Random Write 561K IOPS*

Intel® Optane™	DC
Persistent Mem	nrv

Intel® Optane™ DC Persistent Memory 128GB Module

Intel® 905p Series AIC

480GB PCIe SSD

Capacity128GBProtocolDDR-TForm FactorDDR4ControllerNVMeNVM Type3DXPoint

Endurance 292 PBW (256B Sequential Write)

91 PBW (64B Sequential Write)

Reliability (MTBF) 2M hours

Operating Temperature 32° to 185° F (0° to 85° C)

Performance Sequential Read 6800 MB/s*

Sequential Write 1850 MB/s*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drive Controllers

HARD DRIVE CONTROLLERS

Microsemi SmartHBA2100-4i4e SAS RAID Levels

Card

PCI Bus 8 lanes, PCI Express 3.0

Offers Integrated RAID (0, 1, and 10) **PCI Data Burst Transfer** Half Duplex x8, PCIe, 8000 MB/s

SAS Bandwidth

Rate

Half Duplex 1200 MB/s per lane

PCI Card Type 3.3V Add-in Card **PCI Voltage** 12 V ± 10%

PCI Power 9.8W typical, Airflow min 200 LFM

Bracket Full height and low profile **Certification Level** PCI Express 3.0 compliant

SAS Processor Microsemi SmartIOC 2100 SAS IO Controller **Internal Connectors** One x4 internal mini-SASHD (SFF-8643) One x4 external mini-SASHD (SFF-8644) **External Connectors**

Maximum Number of SCSI 256 Non-RAID SAS/SATA devices

Devices

LED Indicators

Connector for Drive Activity Light NOTE: RAID 5 is not supported on MicroSemi 2100-4i4e 8-port SAS 12Gb/s

RAID Card

Technical Specifications - Graphics

GRAPHICS

NVIDIA® Quadro® P620

2GB Graphics

Form Factor Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P620 Graphics Card

GPU: 512 CUDA cores

Max Power: 40 Watts

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 128-bit Memory Bandwidth: 64 GB/s

Connectors 4mDP Outputs * **Maximum Resolution** DisplayPort™ 1.4:

up to 4x 5120 x 2880 x 24 bpp @ 60Hzsupports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics

Drivers

Windows 11 Windows10

Windows 7 Professional

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes *P620 only have mini-DisplayPort™ (mDP) video ports.

Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters

included

After market option kit:Two mDP-to-DP Adapters included

Additional mDP-to-DP Adapters are available as Factory Configuration or

Option Kit accessories:

- 2MY05AA - HP miniDP-to-DP Adapter Cables

2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Technical Specifications - Graphics

NVIDIA® T400 4GB Graphics

Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot, Low Profile

Weight: 124g

Graphics Controller NVIDIA® T400 Graphics Card

> GPU: 384 CUDA cores Power: 30 Watts Cooling: Active

Bus Type PCI Express 3.0 x16 Memory Size: 4 GB GDDR6

> Memory Interface: 64-bit Memory Bandwidth: 80 GB/s

Connectors 3x mDP

Maximum Resolution 3x 5120 x 2880 x 24 bpp @ 60Hz

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes: CUDA, OpenCL 1.x

Available Graphics

Drivers

Windows 11 Windows 10

Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® Ouadro® P1000 **4GB Graphics**

Form Factor Dimensions:2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P1000 Graphics Card

GPU: 640 NVIDIA® CUDA® cores

Max Power: 47 Watts

Bus Type PCI Express 3.0 x16

Memory Size: 4 GB GDDR5, 2500 MHz

> Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth

Connectors 4mDP Outputs **Maximum Resolution** DisplayPort™ 1.4:

> - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Supported Graphics APIs

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1 OpenGL® 4.5

DirectX® 12

Vulkan™ 1.0



Technical Specifications - Graphics

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics

Drivers

Windows 11 Windows 10

Windows 7 Professional

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

AMD Radeon™ Pro WX 3200 4GB Graphics **Form Factor**

Graphics Controller

Low-Profile Single Slot (2.75 "H x 6.6" L) Radeon™ Pro WX 3200 Graphics Card

GPU: 640 Stream Processors organized into 8 Compute Units

Power: 56 Watts Cooling: Active

Memory 4GB GDDR5 memory

Memory Bandwidth: 96 GB/s Memory Width: 128 bit

Connectors 4x Mini DisplayPort™ 1.4 – HDR ready connectors with HBR3 and MST

support.

Factory Configured: No adapters included

After market option kit: One mDP-to-DP cable adapters included

Additional Mini DisplayPort™-to-DisplayPort™, DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or

Option Kit accessories.

Maximum Resolution 5K support @ 60Hz

• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

4x 4K support @ 60Hz

Image Quality Features Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

Display Output 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture
Supported Graphics APIs

Polaris DirectX°12

OpenGL[®] 4.6 OpenCL[™] 2.0 Vulkan[™] 1.0 Windows 11

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Graphics

Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 2. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro™ and Radeon™ Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 3. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

NVIDIA® T1000 4GB Graphics

Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot

Weight: 132.6 grams

Graphics Controller NVIDIA® T1000 Graphics Card

Power: 50W Cooling: Active

Bus TypePCI Express 3.0 x16MemorySize: 4GB GDDR6

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128-bit 4x mini DisplayPort™ 1.4a

Connectors4x mini DisplayPort™ 1Maximum Resolution7680 x 4320 @ 120Hz

Display Output Maximum number of displays: 4 displays

Architecture NVIDIA® Turing™

Supported Graphics APIs xx

Available Graphics

Drivers

Windows 11 Windows 10

Windows 10

Windows 7 Professional

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 8GB Graphics

Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot

Weight: 132.6 grams

Graphics Controller NVIDIA® T1000 Graphics Card

Power: 50W Cooling: Active



Technical Specifications - Graphics

Bus Type PCI Express 3.0 x16 Memory Size: 8GB GDDR6

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128-bit

Connectors 4x mini DisplayPort™ 1.4a **Maximum Resolution** 7680 x 4320 @ 120Hz

Display Output Maximum number of displays: 4 displays

Architecture NVIDIA® Turing™ **Available Graphics** Windows 11 **Drivers** Windows 10 Windows 8.1

Windows 7 Professional

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A2000 6GB Graphics

Form Factor

Dimensions: 2.713" H x 6.6" L

Dual slot, half-height

Weight: 295 grams (without extender)

NVIDIA® RTX A2000 Graphics Card **Graphics Controller**

> Power: 70W Cooling: Active PCI Express 4.0 x16

Bus Type Memory Size: 6GB GDDR6

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192-bit

Connectors 4x mini-DisplayPort™ 1.4a

Maximum Resolution Up to 4x 5120 x 2880 x 24bpp @ 60Hz

Architecture NVIDIA® Ampere™ Supported Graphics APIs CUDA, OpenCL™ 1.x **Available Graphics** Windows 11

Drivers Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

1. RTX A2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately as AMO:

a. 2MY05AA - HP Single miniDP-to-DP Adapter Cable

2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

2. Two mDP-to-DP adapters are included with the RTX A2000 when it is ordered as an AMO kit.

Technical Specifications - Graphics

NVIDIA® RTX A4000 16GB Graphics **Form Factor** Full-Height Single Slot (4.4" Height x 9.5" Length)

Graphics Controller NVIDIA® RTX A4000 Graphics

GPU: 6144 NVIDIA® CUDA® Parallel Processing Cores

Power: 140 Watts Cooling: Active

Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Connectors 4x DP

One 6-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Display Outputs¹ 4x DP

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A4500 20GB Graphics Form Factor

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller NVIDIA® RTX A4500 Graphics

GPU: 7168 NVIDIA® CUDA® Parallel Processing Cores

Power: 200 Watts Cooling: Active

Memory 20GB GDDR6 memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Technical Specifications - Graphics

Connectors 4x DP

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort[™] to VGA, DisplayPort[™] to DVI, and DisplayPort[™] to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Display Outputs¹ 4x DP

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A5000 24GB Graphics Form Factor

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Graphics Controller

NVIDIA® RTX A5000 GPU: 8192 CUDA Cores

Power: 230W

Cooling: Active

Memory 24GB GDDR6

Memory Bandwidth: Up to 768GB/s ECC Memory (disabled by default)

Connectors DP (x4) with HDR support

One 8-pin auxiliary power connector

After market option Kit: no power adapter included with card.

DisplayPort[™] to VGA, DisplayPort[™] to DVI (single-link and dual-link), and DisplayPort[™] to HDMI adapters available as accessories.

Technical Specifications - Graphics

Maximum Resolution DisplayPort™ 1.4a:

7680x4320 @ 120Hz

Display Outputs 4x DP1.4a HDR2 outputs (up to 7680x4320 @ 120Hz)

GPU Architecture NVIDIA® Ampere™

Supported Graphics

APIs

DirectX®12, OpenGL® 4.5

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10 Windows 7

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters

included

After market option kit: No adapters included

NVIDIA® RTX™ A6000 48GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Graphics Controller NVIDIA® RTX™ A6000 Graphics

GPU: 10752 NVIDIA® CUDA® Parallel Processing Cores

Power: 300 Watts Cooling: Active

Memory 48GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DP 1.4a

Quadro Sync II connector

Ampere NVLink® Stereo Sync

Requires 8-pin CPU auxiliary power

Maximum Resolution 5120x2880 @ 60Hz (up to 4 displays)

Display Outputs 4x DP 1.4 (7680x4320 @ 60Hz)

Supported Graphics APIs DirectX°12, OpenGL° 4.6, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran™

Technical Specifications - Graphics

Available Graphics Drivers Windows 11 Windows 10 Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W5500 8GB Form Factor Full-Height Single Slot

Graphics Controller Architecture: RDNA

GPU: 1408 Stream Processors organized into 22 Compute Units

Power: 125W Cooling: Active

Memory 8GB GDDR6 memory

Memory Bandwidth: up to 224 GB/s

Memory Interface: 128-bit

Display Output Max Displays: 4

Video Outputs: 4x DisplayPort™ 1.4

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Maximum Resolution 7690 x 4320 resolution @ 60Hz

Software API Support DirectX°: 12

OpenGL®: 4.6, OpenCL™: 2.0 Vulkan™ 1.1

Available Graphics

Drivers

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Form Factor Full-Height Double Slot

Technical Specifications - Graphics

AMD Radeon™ Pro W5700 8GB

Graphics Controller Architecture: RDNA

GPU: 2304 Stream Processors organized into 36 Compute Units

Power: 205W Cooling: Active

Memory 8GB GDDR6 memory

Memory Bandwidth: up to 448 GB/s

Memory Interface: 256-bit

Display Output Max Displays: 6

Video Outputs: 5x Mini-DisplayPort™ 1.4 and 1x USB-C

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Maximum Resolution 7690 x 4320 resolution @ 60Hz

Software API Support DirectX[®]: 12

> OpenGL[®]: 4.6, OpenCL™: 2.0 Vulkan™ 1.1

Available Graphics

Drivers

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon ™ Pro W6600 8GB Graphics **Form Factor** Full height, Single Slot, 241mm length

Graphics Controller AMD Radeon™ PR W6600 XT Graphics

> **GPU: AMD RDNA 2** Memory: 8GB GDDR6

Power: 130 Watts, 6-pin Power Cable Cooling: Active, Dual Axial fan

Bus Type PCI Express 4.0 x16

Connectors 4x DisplayPort 1.4 with DSC **Maximum Resolution** DisplayPort™ 1.4 with DSC:

- up to 4x @ 3840x2160px (4K) - up to 4x @ 5120x2880px (5K) - up to 1x @ 7680x4320px (8K)

Display Outputs 4x DP

Shading Architecture

Microsoft DirectX 12 Shader Model 6.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Feature Level 12_1

Technical Specifications - Graphics

Vulkan 1.1 OpenCL 2.2

Available Graphics
Drivers

Windows 11 Windows 10

Linux® 64-bit (selected distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W6800 32GB Form Factor Full-Height Double Slot

Graphics Controller Architecture: RDNA 2

GPU Cores: 3840 Power: 261W

Cooling: Active fan heatsink

Memory 32GB GDDR6 memory

ECC Capable: Yes

Memory Bandwidth: up to 512 GB/s

Memory Interface: 256-bit

Display Output Max Displays: 6

Video Output: 6x Mini-DisplayPort™ 1.4 with DSC

Display Configurations:

5K Resolution: 6x @ 5120 x 2880 resolution @ 60Hz 8K Resolution: 2x @ 7680 x 4320 resolution @60Hz

HDR Support: Yes 8K Support: Yes

Notes: W6800 only has mini-DisplayPort™ (mDP) video ports

- Configure-to-order must specify AV options to add any required mDP-to-DP Adapters
- Two mDP-to-DP Adapters are included in the RTX A2000 AMO kits
- If more mDP-to-DP Adapters are needed, Adapters can be ordered separately as AMO:
 - o 2MY05AA HP Single miniDP-to-DP Adapter Cable
 - 2KW87A6 HP (Bulk 12) miniDP-to-DP Adapter Cables

Bus Type PCI Express x16 Gen4

Software API Support DirectX°: 12

OpenGL®: 4.6, OpenCL™: 2.1 Vulkan: 1.2



Technical Specifications - Graphics

Available Graphics Drivers

Windows 11 Windows 10

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W5500 8GB **Form Factor** Full-Height Single Slot

Graphics Controller Architecture: RDNA

GPU: 1408 Stream Processors organized into 22 Compute Units

Power: 125W Cooling: Active

Memory 8GB GDDR6 memory

Memory Bandwidth: up to 224 GB/s

Memory Interface: 128-bit

Display Output Max Displays: 4

Video Outputs: 4x DisplayPort™ 1.4

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort[™]-to-VGA or DisplayPort[™]-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Maximum Resolution 7690 x 4320 resolution @ 60Hz

Software API Support DirectX[®]: 12

OpenGL[®]: 4.6, OpenCL™: 2.0 Vulkan™ 1.1

Available Graphics

Drivers

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W5700 8GB Form Factor Full-Height Double Slot

Graphics Controller Architecture: RDNA

GPU: 2304 Stream Processors organized into 36 Compute Units

Power: 205W Cooling: Active



Technical Specifications - Graphics

Memory 8GB GDDR6 memory

Memory Bandwidth: up to 448 GB/s

Memory Interface: 256-bit

Display Output Max Displays: 6

Video Outputs: 5x Mini-DisplayPort™ 1.4 and 1x USB-C

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Maximum Resolution 7690 x 4320 resolution @ 60Hz

Software API Support DirectX°: 12

OpenGL[®]: 4.6, OpenCL™: 2.0 Vulkan™ 1.1

Available Graphics

Drivers

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W6800 32GB Form Factor Full-Height Double Slot

Graphics Controller Architecture: RDNA 2

GPU Cores: 3840 Power: 261W

Cooling: Active fan heatsink

Memory 32GB GDDR6 memory

ECC Capable: Yes

Memory Bandwidth: up to 512 GB/s

Memory Interface: 256-bit

Display Output Max Displays: 6

Video Output: 6x Mini-DisplayPort™ 1.4 with DSC

Display Configurations:

5K Resolution: 6x @ 5120 x 2880 resolution @ 60Hz 8K Resolution: 2x @ 7680 x 4320 resolution @60Hz

HDR Support: Yes 8K Support: Yes



Technical Specifications - Graphics

Notes: W6800 only has mini-DisplayPort™ (mDP) video ports

- Configure-to-order must specify AV options to add any required mDP-to-DP Adapters
- Two mDP-to-DP Adapters are included in the RTX A2000 AMO kits
- If more mDP-to-DP Adapters are needed, Adapters can be ordered separately as AMO:
 - 2MY05AA HP Single miniDP-to-DP Adapter Cable
 - o 2KW87A6 HP (Bulk 12) miniDP-to-DP Adapter Cables

Bus Type PCI Express x16 Gen4

Software API Support DirectX[®]: 12

OpenGL®: 4.6, OpenCL™: 2.1 Vulkan: 1.2

Available Graphics Drivers

Windows 11 Windows 10

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications – Optical and Removable Storage

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim DVD Writer

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R **DVD-RW** CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

> Full Stroke DVD < 200 ms (seek) Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

> DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

> 5 VDC ± 5%-100 mV ripple p-p **DC Power Requirements**

DC Current 5 VDC -< 800 mA typical, <1600 mA

maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity Maximum Wet Bulb Temperature

10% to 80% 84° F (29° C)

Operating Systems Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit.

Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

* No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP SATA DVD Writer drive, installation guide.

HP 9.5mm Slim DVD-ROM Description

Drive

9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA / ATAPI

Technical Specifications – Optical and Removable Storage

Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

CD-ROM Mode 1 < 110 ms (typical)
Full Stroke DVD < 230 ms (typical)
Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

DC Power Requirements $5 \text{ VDC} \pm 5\%-100 \text{ mV ripple p-p}$ DC Current 5 VDC - <800 mA typical, < 1600 mA

maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

Operating Systems Windows 11, Windows 10, Windows 7 Professional 64-bit

Supported Red Hat® Enterprise Linux®(RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

HP HH DVD Writer (16X RW DVD-R)

Description HP Half Height DVD Writer

Mounting Orientation Either Horizontal or vertical

Interface Type SATA

Dimensions (WxHxD) 146x42x165mm

Supported Media Types DVD+R

Rates

DVD+RW DVD+R DL DVD-R DL DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Full Stroke DVD 145ms (seek)
Full Stroke CD 120ms (seek)

Maximum Data Transfer CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 13X

DVD-RW Up to 13X DVD+R DL Up to 12X DVD-R DL Up to 12X DVD-ROM Up to 12X DVD-ROM DL Up to 12X

Technical Specifications – Optical and Removable Storage

DVD+R Up to 16X DVD-R Up to 16X

Power Source SATA DC power receptacle

> **DC Power Requirements** $5 \text{ VDC} \pm 5\% - 100 \text{ mV ripple p-p}$

> > 12 VDC ± 10% -200 mV ripple p-p

DC Current 5 VDC -<1500mA typical, <2000 mA

maximum.

Operating Environmental Temperature

(all conditions noncondensing)

Relative Humidity

41° to 122° F (5° to 50° C) 10% to 90% (Non-Condensing)

Operating Systems

Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit. Red Hat

Enterprise Linux WS4**,5,6 Desktop/Workstation.

No driver is required for this device, Native support is provided by

operating system.

Kit Contents HP SATA DVD Writer drive, Installation guide.

HP 9.5mm Slim BDXL Blu- Description **Ray Writer**

9.5mm height, tray-load

Mounting Orientation

Either horizontal or vertical

Interface Type

SATA/ATAPI

Dimensions (WxHxD)

128 x 9.5 x 127mm

Supported Media Types

BD-ROM BD-R **BD-RE**

DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R **DVD-RW**

CD-R CD-RW

Disc Capacity DVD-ROM

Blu-ray 25 GB (single-layer)

50 GB (dual-layer) 100/128 GB (BDXL)

8.5 GB DL or 4.7 GB standard

Full Stroke DVD < 230 ms (seek) Full Stroke CD < 220 ms (seek)

Blu-ray < 230 ms (seek) (Full Stroke Blu-ray) Startup Time (Time to drive ready from tray

loading)

BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 185 / 185 DVD-R (SL/DL) 255 / 255

DVD-RW **25S**

DVD+R (SL/DL) 255 / 255

DVD+RW **25S**



Technical Specifications – Optical and Removable Storage

CD-ROM **15S**

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X BD-ROM Up to 6X

Blu-ray

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

41° to 122° F (5° to 50° C)

SATA DC power receptacle Power Source

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p **DC Current** 5 VDC -900 mA typical, 2000mA

> > maximum

Operating Environmental Temperature

(all conditions noncondensing)

Relative Humidity

10% to 80% 84° F (29° C)

Maximum Wet Bulb Temperature

Operating Systems Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit Red Hat® Enterprise Linux® (RHEL) 6, 7 Desktop/Workstation

SUSE Linux® Enterprise Desktop 12

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

HP SD Card Reader

Description Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports SD 4-bit parallel transfer mode

Interface Type

USB 3.1 GEN 1 High-speed interface

Dimensions (WxHxD)

1.15 x .9 x .15 in (29.00 x 23.6 x 3.15 mm) Fits conveniently in the Front IO

Bay

Supported Media Types

Secure Digital Card (SD)

Secure Digital High Capacity (SDHC)

SD Extended Capacity Memory Card (SDXC)

Technical Specifications – Optical and Removable Storage

SD Ultra High Speed II(SD UHSII)

These additional media types are supported with a card adapter.

Memory Stick Micro (M2)

miniSD

miniSD High Capacity

Micro SD Memory Card (MicroSD)

Micro SD High Capacity Memory Card (MicroSDHC)

Test Parameters/Conditions - Power applied, unit operating on system

±5%

Operating Systems
Supported

Windows 11, Windows 10

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents Media card reader

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel® Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

Weight 0.35 lbs. (0.16 kg)



Technical Specifications - Controller Cards

CONTROLLER CARDS

HP Thunderbolt-3 Dual Port2 PCIe 1-port I/O Card Data Transfer Rate Supports up to 40 Gb/s (40,000 Mb/s)

Devices Supported Thunderbolt™, Thunderbolt™ 2 and Thunderbolt™ 3 certified for Windows

devices

Bus Type PCIe card, full height PCIe slots

Ports Two Thunderbolt™ 3 external USB type-C output connectors (Rear)

Two full size DisplayPort input connectors (Rear)

Internal Connectors One 2x5-Pin header connector

System Requirements Windows 11, Windows 10 Professional, available dedicated PCH PCIe slot.

Temperature - Operating 50° to 131° F (10° to 55° C) **Temperature - Storage** -22° to 140° F (-30° to 60° C)

Relative Humidity -

Operating

20% to 80%

Compliances FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998 STD,

Taiwan BSMI CNS13438, Korea MIC

Operating Systems

Supported

Windows 11, Windows 10 Professional.

Kit Contents HP Thunderbolt™ 3 Dual Port PCIe I/O Card, 2- DisplayPort cables, GPIO

(General-Purpose Input/Output) cables, Installation documentation and

warranty card.



^{*}Maximum speed requires DisplayPort™ and PCIe aggregation.

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

Integrated Intel® I219LM Connector **RJ-45**

> Intel® I219LM Controller **Data Rates Supported** 10/100/1000 Mbps

Boot ROM Support PXE, UEFI

Connect Speed LED Indicators

Off = No link

Blinking = Activity

Speed LED

Link/Activity LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Intel® Active Management Technology™ 11

Integrated Intel® X722 for 1GbE

Connector 1 RJ-45

Controller Intel® X722 for 1GbE

Data Rates Supported 1000 Mbps **Boot ROM Support** PXE, UEFI

Connect Speed LED Indicators

Off = No link Blinking = Activity

Speed LED

Link/Activity LED

Off = No Link

Green = 1000Mbps

Cabled from Dedicated Rear I/O Slot

Management Capabilities Wake-On-LAN

HPZ Dual 10GbE Network Networking Interface

Module

2 RJ-45

System Interface Networking Speeds

1Gbps, 10Gbps

Supported

Cabling (up to 100m)

Cat5e (or higher) for 1Gbps Cat6a (or higher) for 10Gbps

Power Consumption (active-typical)

5.5W at 1Gbps 11.2W at 10Gbps

Physical Dimensions

0.875 in x 3 in x 2.75 in

Connect Speed LED

Link/Activity LED

Indicators

Off = No link Blinking = Activity

Speed LED

Amber = 1Gbps

Green = 10Gbps

0 °C to 55 °C (32 °F to 131 °F) **Operating Temperature**

Intel® I210-T1 **Networking Interface**



1 RJ-45

System Interface

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

PCI Express 2.1 x1

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

0.81W

Physical Dimensions

Length: 6.7cm (2.64 inches)

(Bracket) Width: 1.8cm (0.709 inches)

Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

Connect Speed LED Indicators

Link/Activity LED

• Off = No link

• Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI.

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T2

Networking Interface

2 RJ-45

System Interface Networking Speeds PCI Express 2.1 x4

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m)

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

4.4W

Power Consumption (active-typical)

4.400

Physical Dimensions

Length: 13.54cm (5.33 inches) Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature $0 \, ^{\circ}\text{C}$ to 55 $^{\circ}\text{C}$ (32 $^{\circ}\text{F}$ to 131 $^{\circ}\text{F}$)

Hardware Certifications USA: FCC B,

EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T4 Networking Interface 4 RJ-45

System Interface

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

PCI Express 2.1 x4

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

Physical Dimensions

Length: 13.54cm (5.33 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

• Off = No link

• Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

Hardware Certifications

0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B, EU: UL CE, Japan: VCCI,

Taiwan: BSMI, Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Aguantia® AQN-108 Networking Interface RJ-45

System Interface

PCI Express 3 x1

Networking Speeds

I CI Expicos 5 X i

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps

Cabling (up to 100m)

Power Consumption

Cat5e (or higher) for all speeds

(active-typical)

3.5W at 5Gbps, 3.0W at 2.5Gbps

Physical Dimensions

3.72 in x 3.18 in (without bracket)

Connect Speed LED Indicators

Link/Activity LED

- Off = No link
- Blinking = Activity

Speed LED

- Off = No link
- Amber = <5Gbps
- Green = 5Gbps

Operating Temperature Hardware Certifications 0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B, EU: UL CE,

Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® X550-T2

Networking Interface

2 x RJ-45

System Interface

PCI Express 3 x4

Networking Speeds

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cabling (up to 100m)

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

Power Consumption (active-typical)

3.9W at 100Mbps 5.5W at 1Gbps

11.2W at 10Gbps

Physical Dimensions

Connect Speed LED

Indicators

Link/Activity LED

Off = No link

• OH - NO UHK

Blinking = Activity

5.2 in x 2.7 in (without bracket)

Speed LED

• Off = No link

Amber = <10Gbps

Green = 10Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC Network Interface System Interface Networking Speeds Supported 1Gb LC Fiber 850 nm

PCIeG2 x1, Half Height, Half Length

1000Base-X (1Gbps)

Cabling 50/125 μm (core/cladding) multimode fiber optic cable up to 500m

62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m

Power Consumption

(active- typical)
Physical Dimensions
Connect Speed LED

Indicators

Operating Temperature
Hardware Certifications

1.5 Watts

8.8 cm x 6.9 cm (3.5 in x 2.7 in) ON: 1Gbps Link OFF: Link down

-25°C to 70°C (-13°F to 158°F)

ons | IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANS), IEEE 802.2 (LLC),

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE

802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Allied Telesis AT-2911T/2-901 Networking Interface 2 RJ-45

System Interface PCI Express 3 x1

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

2.4W

Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption

(active-typical)
Physical Dimensions

Length: 8.8cm (3.5 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED

Indicators

Link/Activity LED

• Off = No link
Blinking = Activity

Operating Temperature

0 °C to 40 °C (32 °F to 104 °F)

Hardware Certifications USA: FCC B,

EU: UL CE, UKCA Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® X710-DA2 10GBASE-SR Converged Network Adapter Networking Interface

2 SFP+ Ports for LC SFP+ Transceivers

System Interface P
Networking Speeds 1

PCI Express 3.0 x8

Supported

10Gbps (or 1Gbps with 3rd party transceiver)

Cabling

LC fiber optic cabling with LC SFP+ Transceivers

Power Consumption

4.3W

(active-typical)
Physical Dimensions

6.578 in x 2.703 in

Connect Speed LED Indicators

Link/Activity LED

Off = No link

• Blinking = Activity

Speed LED

Off = 10MbpsGreen = 100MbpsAmber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

NOTE: Windows 7 is NOT supported

10GbE SFP+ SR Transceiver **Connector Type** LC

Cable Type 62.5/125um or 50/125um (core/cladding), graded-index, low metal

content, multimode fiber optic, complying with ITU-T G.651 and ISO/IEC

793-2 Type A1b or A1a, respectively.

Cable Length2-300mWavelength850nmForm FactorSFP+

Physical Dimensions 0.47(h) x 0.54(w) x 2.19(d) inches

(1.19 x 1.38 x 5.57 cm) 0C to 45C (32F to 113F)

Operating Temperature

Operating Humidity 0% to 85%, noncondensing

NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC **Connector** 2 x SFP28 Transceiver Cage (Dual Port)*

Cabling Depends on transceiver pairing. Typically OM4 or higher MMF LC fiber optic

cabling with LC SFP28 Transceivers.

Controller ConnectX6-DX

Memory 256Mbit SPI Quad Flash Device

Data Rates Supported 1/10/25GbE

Compliance – IEEE 802.3by 25 Gigabit Ethernet – IEEE 802.3ae 10 Gigabit Ethernet

- IEEE 802.3ap based auto-negotiation and KR startup

– IEEE 802.3ad, 802.1AX Link Aggregation – IEEE 802.1Q, 802.1P VLAN tags and priority

- IEEE 802.1Qau (QCN)- Congestion Notification- IEEE 802.1Qaz (ETS)- IEEE 802.1Qbb (PFC)- IEEE 802.1Qbg

– IEEE 802.1Qbg – IEEE 1588v2

– Jumbo frame support (9.6KB)

Technical Specifications - Networking and Communications

Safety: CB/cTUVus/CE

- EMC: CE/FCC/VCCI/ICES/RCM

- RoHS Compliant

Bus Architecture PCIe Gen 4 x8

Data Transfer Mode PCI Express - stores and accesses Ethernet fabric connection information

and packet data

Power Requirements 11.5 Watts (typical) **Network Transfer Rate** 1Gbps, 10Gbps, 25Gbps

NOTE: Network Transfer Rate depends on transceiver model.*

Kit Contents NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

*Transceivers sold separately. You must have a transceiver installed in order to connect this card to a network.

Intel® 8265 WLAN Networking Speeds 802.11ac MU-MIMO (up to 867 Mbps)

Bluetooth 4.2

IEEE WLAN Standard IEEE 802.11a/b/g/n/ac, 802.11d, 802.11e, 802.11h, 802.11i, 802.11w;

802.11r, 802.11k, 802.11v pending

Bluetooth 4.2

System Interface PCI Express 2.1 x1

Antenna 2x2

Summary of Changes

SUMMARY OF CHANGES

Date of change:	Version History:		Description of change:
November 1, 2017	From v1 to v2	Added	HP DisplayPort to HDMI Adapter, HP DisplayPort to VGA Adapter, NVIDIA SLI
			3-slot Graphics Connector and NVIDIA Quadro Sync II to Graphics section
			and Microsemi 3152-8i SAS ROC RAID Controller
		Changed	Graphics, Storage / Hard Drives and Memory sections, changed Front and
			internal view info on the Overview section, changed Operating Systems
			section, changed System Board section, Physical Security and Serviceability
			sections
November 29, 2017	From v2 to v3	Added	Processors, hard drives and graphics to offerings, added Declared Noise Emissions information
January 30, 2018	From v3 to v4	Removed	NVIDIA SLI Graphics Connectors from Graphics Cable Adapters section
March 27, 2018	From v4 to v5	Added	Intel Xeon processors added
	From v5 to v6	Removed	RAID 5
April 16, 2018	+		
August 13, 2018	From v6 to v7	Added	Footnote to Networking and Communications section
Contombou 4 2010	F	Changed	Processors section and Operating Systems section
September 4, 2018	From v7 to v8	Removed	HP IEEE 1394b FireWire PCIe Card
September 6, 2018	From v8 to v9	Removed	Microsemi 3152-8i SAS ROC RAID Controller
September 21, 2018	From v9 to v10	Added	Intel Optane SSD 905p AiC 280GB & 480GB
	From v10 to v11	Changed	NVIDIA Quadro P6000 Graphics specs
April 8, 2019	From v11 to v12	Added	New Intel Xeon Processors and graphics, added HP DX175 Removable HDD
			Carrier into the HDD Frame/Carriers section
		Changed	Storage / Hard Drives, Memory sections and format changes
May 15, 2019	From v12 to v13	Added	NVIDIA Quadro RTX 8000 48GB Graphics
		Changed	External BIOS simulator link on Physical Security and Serviceability section
		Removed	Intel 9260 WLAN
June 12, 2019	From v13 to v14	Changed	Storage section Storage Section
July 7, 2019	From v14 to v15	Added	Intel Xeon W Processors
July 15, 2019	From v15 to v16	Changed	Corrected Intel 905p Series AIC 480GB PCIe SSD
August 1, 2019	From v16 to v17	Changed	Processors Matrix
September 1, 2019	From v17 to v18	Added	Footnote to Memory section, Added Optane 905P 380GB M.2 SSD Module,
			HP Z Turbo Drive 1TB SED TLC Z4/Z6 G4 SSD Kit & module to Storage
			section, Added Intel® Wi-Fi 6 AX200 & BT PCIe to Networking section
October 26, 2019	From v18 to v19	Changed	Graphics section
November 1, 2019	From v19 to v20	Added	NVDIMM Memory sections, Added HP QX310 Removable NVMe
			Frame/Carrier w/PCIe card to Optical and Removable Storage section
January 2, 2020	From v20 to v21	Changed	Storage section
February 26, 2020	From v21 to v22	Added	New Intel Xeon Processors
		Changed	Overview, PCIe Solid State Drives sections
April 2, 2020	From v22 to v23	Changed	Processors and NVDIMM Memory sections
July 18, 2020	From v23 to v24	Changed	Processors, Graphics section
January 5, 2021	From v24 to v25	Changed	Processors, Memory, Graphics, Racking and Physical Security, Operating
			Systems and Hard Drives sections
February 1, 2021	From v25 to v26	Changed	NETWORKING AND COMMUNICATIONS section
March 1, 2021	From v26 to v27	Changed	Overview section
April 13, 2021	From v27 to v28	Changed	Processors, Graphics and Social and Environmental Responsibility sections
May 1, 2021	From v28 to v29	Changed	Graphics section
June 1, 2021	From v29 to v30	Changed	Memory and Graphics sections
July 1, 2021	From v30 to v31	Changed	Graphics section
August 1, 2021	From v31 to v32	Changed	Graphics section
September 1, 2021	From v32 to v33	Changed	Input Devices and Graphics sections
October 1, 2021	From v33 to v34	Changed	Graphics and System Board sections



Summary of Changes

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November 1, 2021	From v34 to v35	Changed	Processors and Graphics sections
December 1, 2021	From v35 to v36	Changed	Operating Systems, Graphics, Networking and Communications and Input
			Devices sections
December 15, 2021	From v36 to v37	Changed	OPERATING SYSTEM and Social and Environmental Responsibility sections
January 1, 2022	From v37 to v38	Changed	Graphics, OPERATING SYSTEM and Application Software sections
February 1, 2022	From v38 to v39	Changed	Input Devices section
March 1, 2022	From v39 to v40	Changed	Graphics, Social and Environmental Responsibility sections
April 1, 2022	From v40 to v41	Changed	Processors, Graphics and Stable & Consistent Offerings sections
May 2, 2022	From v41 to v42	Changed	Graphics section
June 1, 2022	From v42 to v43	Changed	Graphics, Networking and Communications sections
July 1, 2022	From v43 to v44	Changed	Graphics section
August 1, 2022	From v44 to v45	Changed	NETWORKING AND COMMUNICATIONS section
September 1, 2022	From v45 to v46	Changed	Format page 18
October 1, 2022	From v46 to v47	Changed	Graphics section
December 1, 2022	From v47 to v48	Changed	Input Devices section
December 9, 2022	From v48 to v49	Changed	Optical and Removable Storage section
January 1, 2023	From v49 to v50	Changed	Networking and Communications, GRAPHICS sections
February 1, 2023	From v50 to v51	Changed	Other Hardware section
March 1, 2023	From v51 to v52	Changed	Manageability section
April 1, 2023	From v52 to v53	Changed	Processors and Graphics sections
May 1, 2023	From v53 to v54	Changed	Other Hardware section
June 1, 2023	From v54 to v55	Changed	Graphics section
July 1, 2023	From v55 to v56	Changed	Networking and Communications, Other Hardware sections
August 1, 2023	From v56 to v57	Changed	Social and Environmental Responsibility section
November 1, 2023	From v57 to v58	Changed	Social and Environmental Responsibility section
April 1, 2024	From v58 to v59	Changed	Other Hardware section



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